

Configurable PMIC, Five-Channel Buck Regulator Plus One-Boost with HyperLight Load<sup>®</sup> and I<sup>2</sup>C Control

### **General Description**

The MIC7400 is a powerful, highly integrated, configurable, power-management IC (PMIC) featuring five synchronous buck regulators, one boost regulator and high-speed  $I^2C$  interface with an internal EEPROM.

The device offers two distinct modes of operation "standby mode" and "normal mode" intended to provide an energy optimized solution suitable for portable handheld, and infotainment applications.

In normal mode, the programmable switching converters can be configured to support a variety of features, including start-up sequencing, timing, soft-start ramp, output voltage levels, current limit levels and output discharge for each channel.

In stand-by mode the PMIC can configured in a low power state by either disabling an output or by changing the output voltage to a lower level. Independent exit from stand-by mode can be achieved either by I<sup>2</sup>C communication or the external STBY pin.

The device has five synchronous buck regulators with high-speed adaptive on-time control supporting even the challenging ultra-fast transient requirement for Core supplies. One boost regulator provides a flash-memory programming supply that delivers up to 200mA of output current. The boost is equipped with an output disconnect switch that opens if a short-to-ground fault is detected.

An internal EEPROM enables a single-chip solution across many platforms by allowing the designer to customize the PMIC for their design. Modifications can be made without the need to re-approve a new PMIC, saving valuable design resources and time.

All switchers provide light-load efficiency with HyperLight Load<sup>®</sup> mode for buck and PFM mode for boost. An additional benefit of this proprietary architecture is very-low output ripple voltage throughout the entire load range with the use of small output capacitors. The MIC7400 is designed for use with a small inductors (down to 0.47µH for buck, 1.5µH for boost), and an output capacitor as small as 10µF for buck, enabling a total solution size of 15mm × 15mm and less than 1mm height.

The datasheet and other support documentation can be found on Micrel's website at: <u>www.micrel.com</u>.

### Features

- Input voltage: 2.4V to 5.5V
- Five independent synchronous bucks up to 3A
- One independent non-synchronous boost 200mA
- 200µA quiescent current (all regulators on)
- 93% peak buck efficiency, 85% typical efficiency at 1mA
- Dual power mode: stand-by and normal mode
- I<sup>2</sup>C interface up to 3.4MHz
- I<sup>2</sup>C on-the-fly EEPROM programmability, featuring:
  - Buck and boost output voltage scaling
  - Power-on-reset threshold and delay
  - Power-up sequencing/sequencing delay
  - Buck and boost current limit
  - Buck and boost pull-down when disabled
  - Individual ON, OFF, and standby modes
  - Soft-start and global power-good masking
- 23µA buck typical quiescent current
- 70µA boost typical quiescent current
- 1.5% output accuracy over temperature/line/load
- 2.0MHz boost switching frequency
- 1.3MHz buck operation in continuous mode
- Ultra-fast buck transient response
- 15mm × 15mm × 1.25mm solution size
- · Thermal-shutdown and current-limit protection
- 36-pin 4.5mm × 4.5mm × 0.85mm FQFN package (0.4mm pitch)
- -40°C to +125°C junction temperature range

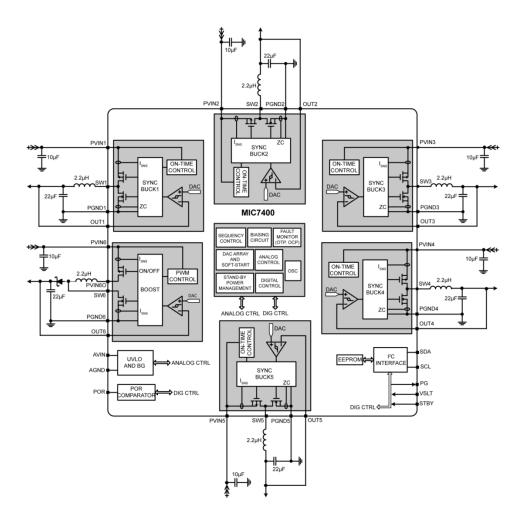
#### **Applications**

- Client and enterprise solid state drives (SSD)
- Consumer and in-vehicle infotainment devices
- Multimedia devices
- Portable handheld devices
- Security camera
- Gaming machines
- · Service provider gateways

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HyperLight Load is a registered trademark of Micrel, Inc.

# **Typical Application**



## **Ordering Information**

Part Number	Marking	Output Voltages	Features	Package <sup>(1)</sup>	Lead Finish
MIC7400YFL	7400 YWWS	1.8V, 1.1V, 1.8V 1.05V, 1.25V, 12V	STBY – Active Low Falling Edge (DEFAULT)	36-Pin 4.5mm × 4.5mm FQFN	Pb- Free
MIC7400-XXXXYFL <sup>(2)</sup>	X X 7400 X YYWW X	Configurable	Configurable	36-Pin 4.5mm × 4.5mm FQFN	Pb- Free

Notes:

1. GREEN, RoHS-compliant package. Lead finish is Matte Tin. Mold compound is Halogen Free.

2. Configurable options available upon request. Contact Marketing.

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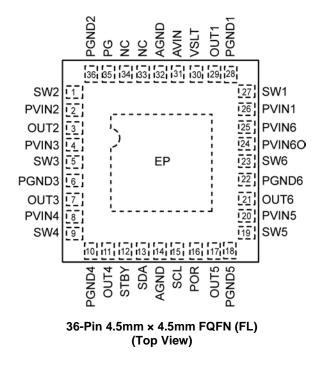
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## **Pin Configuration**



### **Pin Description**

Pin Number	Pin Name	Description
1	SW2	Switch Pin 2 (Output): Inductor connection for the synchronous step-down regulator. Connect the inductor between the output capacitor and the SW2 pin.
2	PVIN2	Power Supply Voltage 2 (Input): Input supply to the source of the internal high-side P-channel MOSFET. An input capacitor between PVIN2 and the power ground PGND2 pin is required and to be placed as close as possible to the IC.
3	OUT2	Output Voltage Sense 2 (Input): This pin is used to sense the output voltage. Connect OUT2 as close to the output capacitor as possible to sense output voltage. Also provides the path to discharge the output through an internal $90\Omega$ resistor when disabled. This pull-down feature is programmed through the PULLD[x] register.
4	PVIN3	Power Supply Voltage 3 (Input): Input supply to the source of the internal high-side P-channel MOSFET. An input capacitor between PVIN3 and the power ground PGND3 pin is required and to be placed as close as possible to the IC.
5	SW3	Switch Pin 3 (Output): Inductor connection for the synchronous step-down regulator. Connect the inductor between the output capacitor and the SW3 pin.
6	PGND3	Power Ground 3: The power ground for the synchronous buck converter power stage. The PGND pin connects to the sources of the internal low-side N-Channel MOSFET, the negative terminals of input capacitors, and the negative terminals of output capacitors.
7	OUT3	Output Voltage Sense 3 (Input): This pin is used to sense the output voltage. Connect OUT3 as close to the output capacitor as possible to sense output voltage. Also provides the path to discharge the output through an internal $90\Omega$ resistor when disabled. This pull-down feature is programmed through the PULLD[x] register.
8	PVIN4	Power Supply Voltage 4 (Input): Input supply to the source of the internal high-side P-channel MOSFET. An input capacitor between PVIN4 and the power ground PGND4 pin is required and to be placed as close as possible to the IC.

# **Pin Description (Continued)**

Pin Number	Pin Name	Description
9	SW4	Switch Pin 4 (Output): Inductor connection for the synchronous step-down regulator. Connect the inductor between the output capacitor and the SW4 pin.
10	PGND4	Power Ground 4: The power ground for the synchronous buck converter power stage. The PGND pin connects to the source of the internal low-side N-Channel MOSFET, the negative terminals of input capacitors, and the negative terminals of output capacitors.
11	OUT4	Output Voltage Sense 4 (Input): This pin is used to sense the output voltage. Connect the OUT4 as close to the output capacitor as possible to sense output voltage. Also provides the path to discharge the output through an internal $90\Omega$ resistor when disabled. This pull-down feature is programmed through the PULLD[x] register.
12	STBY	Standby Reset (Input): Standby mode allows the total power consumption to be reduced by either lowering a supply voltage or turning it off. The IC can be placed in standby mode while operating in normal mode by a high-to-low transition (DEFAULT) on the STBY input. When this occurs, the STBY_MODEB bit will be set to logic "0". Either a low-to-high transition on the STBY pin or an I <sup>2</sup> C write command to the STBY_MODEB bit sets all of the regulators to their normal mode default settings. This pin can be driven with either a digital signal or open collector output. Do not let this pin float. Connect to ground or V <sub>IN</sub> . A pull-down resistor of 100k $\Omega$ or less can also be used. There are both a high-to-low (DEFAULT) and low-to-high normal to standby trigger options available.
13	SDA	High-Speed Mode 3.4MHz I <sup>2</sup> C Data (Input/Output): This is an open drain, bidirectional data pin. Data is read on the rising edge of the SCL and data is clocked out on the falling edge of the SCL. External pull-up resistors are required.
14	AGND	Analog Ground: Internal signal ground for all low power circuits. Connect to ground plane for best operation.
15	SCL	High-Speed Mode 3.4MHz I <sup>2</sup> C Clock (Input): I <sup>2</sup> C serial clock line open drain input. External pull-up resistors are required.
16	POR	Power-on-Reset (Output): This is an open drain output that goes high after the POR delay time elapses. The POR delay time starts as soon as the AVIN pin voltage rises above the upper threshold set by the PORUP register. The POR output goes low without delay when AVIN falls below the lower threshold set by the PORDN register.
17	OUT5	Output Voltage Sense 5 (Input): This pin is used to sense the output voltage. Connect OUT5 as close to the output capacitor as possible to sense output voltage. Also provides the path to discharge the output through an internal $90\Omega$ resistor when disabled. This pull-down feature is programmed through the PULLD[x] register.
18	PGND5	Power Ground 5: The power ground for the synchronous buck converter power stage. The PGND pin connects to the source of the internal low-side N-Channel MOSFET, the negative terminals of input capacitors, and the negative terminals of output capacitors.
19	SW5	Switch Pin 5 (Output): Inductor connection for the synchronous step-down regulator. Connect the inductor between the output capacitor and the SW5 pin.
20	PVIN5	Power Supply Voltage 5 (Input): Input supply to the source of the internal high-side P-channel MOSFET. An input capacitor between PVIN5 and the power ground PGND5 pin is required and to be placed as close as possible to the IC.
21	OUT6	Output Voltage 6 Sense (Input): This pin is used to sense the output voltage. Connect OUT6 as close to the output capacitor as possible to sense output voltage. Also provides the path to discharge the output through an internal programmable current source when disabled. This pull-down feature is programmed through the PULLD[x] register.
22	PGND6	Power Ground 6: The power ground for the boost converter power stage. The PGND pin connects to the source of the internal low-side N-Channel MOSFET, the negative terminals of input capacitors, and the negative terminals of output capacitors.
23	SW6	Switch Pin 6 (Input): Inductor connection for the boost regulator. Connect the inductor between the PVIN6O and SW6 pin.

# **Pin Description (Continued)**

24         Power Supply Voltage 6 (Output): This pin is the output of the power disconnect switch for the boost inductor. In shutdown, an internal Wich provides a current path for the boost output from the input supply. This feature eliminates current draw from the input supply during shutdown. An input capacitor between PVINBO and the power ground PGNDb pin is required and place as close as possible to the IC.           25         PVIN6         Power Supply Voltage 6 (Input): Input supply to the internal disconnect switch.           26         PVIN1         Power Supply Voltage 6 (Input): Input supply to the source of the internal high-side P-channel MOSFET An input capacitor between PVIN1 and the power ground PGNDT pin is required and to be placed as close as a possible to the IC.           27         SW1         Switch Pin 1 (Output): Inductor connection for the synchronous step-down regulator. Connect the inductor between the output capacitor and the SW1 pin.           28         PGND1         Power Supply voltage Signal with and the synchronous buck converter power stage. The PGND pin connects to the source of the internal low-side N-Channel MOSFET, the negative terminals of output capacitors.           29         OUT1         Output Voltage Sense 1(Input): This pin is used to sense the output voltage remotely. Connect OUT1 as close to output capacitor as possible to sense output voltage. The FoRD pin connects to the output capacitors.           30         VSLT         POR Selection Threshold (Input): This pin is used to sense the output voltage remotely. Connect OUT1 as close to output capacitor spossible to sense output voltage. The pull-down feature is programmed through the PULLD[X] register.	Pin Number	Pin Name	Description
26         PVIN1         Power Supply Voltage 1 (Input): Input supply to the source of the internal high-side P-channel MOSFET. An input capacitor between PVIN1 and the power ground PGND1 pin is required and to be placed as close as possible to the IC.           27         SW1         Switch Pin 1 (Output): Inductor connection for the synchronous step-down regulator. Connect the inductor between the output capacitor and the SW1 pin.           28         PGND1         Power Ground 1: The power ground for the synchronous buck converter power stage. The PGND pin connects to the source of the internal low-side N-Channel MOSFET, the negative terminals of input capacitors, and the negative terminals of output capacitors.           29         OUT1         Output Voltage Sense 1(Input): This pin is used to sense the output voltage remotely. Connect OUT1 as close to output capacitors ap cosible to sense output voltage. This feature also provides the path to discharge the output through an internal 900 resistor when disabled. The pull-down feature is programmed through the PULLD[x] register.           30         VSLT         POR Selection Threshold (Input): The start-up sequence begins as soon as the AVIN pin voltage rises above the IC's UVLO upper threshold. The outputs do not turn off until AVIN pin voltage falls below the lower threshold limit. A 2.2µF ceramic capacitor from the AVIN pin to AGND pin must be placed next to the IC.           32         AGND         Analog Ground: Internal signal ground for all low power circuits. Connect directly to the layer 2 ground plane. Layer 2 is the point where all the PGNDs and AGND are connected. Do not connect PGND and AGND together on the top layer.           33         NC	24	PVIN6O	regulator. When the boost regulator is on, an internal switch provides a current path for the boost inductor. In shutdown, an internal P-channel MOSFET is turned off and disconnects the boost output from the input supply. This feature eliminates current draw from the input supply during shutdown. An input capacitor between PVIN6O and the power ground PGND6 pin is required and place as close as
26         PVIN1         MOSFET: An input capacitor between PVIN1 and the power ground PGND1 pin is required and to be placed as close as possible to the IC.           27         SW1         Switch Pin 1 (Output): Inductor connection for the synchronous step-down regulator. Connect the inductor between the output capacitor and the SW1 pin.           28         PGND1         Power Ground 1: The power ground for the synchronous buck converter power stage. The PGND pin connects to the source of the internal low-side N-Channel MOSFET, the negative terminals of input capacitors, and the negative terminals of output capacitors.           29         OUT1         Output Voltage Sense 1(Input): This pin is used to sense the output voltage remotely. Connect OUT1 as close to output capacitor as possible to sense output voltage. This feature also provides the path to discharge the output through an internal 900 resistor when disabled. The pull-down feature is programmed through the PULLD[x] register.           30         VSLT         POR Selection Threshold (Input): A high on this pin sets the PORUP and PORDN registers to their upper threshold limits. Analog Voltage Supply (Input): The start-up sequence begins as son as the AVIN pin voltage rises above the IC's UVLO upper threshold. The outputs do not turn off until AVIN pin voltage fails below the lower threshold limit. A 2.2µF ceramic capacitor from the AVIN pin to AGND pin must be placed next to the IC.           32         AGND         Analog Ground: Internal signal ground for all low power circuits. Connect directly to the layer 2 ground plane. Layer 2 is the point where all the PGNDs and AGND are connected. Do not connect PGND and AGND together on the top layer.           33	25	PVIN6	Power Supply Voltage 6 (Input): Input supply to the internal disconnect switch.
27       SW1       inductor between the output capacitor and the SW1 pin.         28       PGND1       Power Ground 1: The power ground for the synchronous buck converter power stage. The PGND pin connects to the source of the internal low-side N-Channel MOSFET, the negative terminals of input capacitors, and the negative terminals of output capacitors.         29       OUT1       Output Voltage Sense 1(Input): This pin is used to sense the output voltage remotely. Connect OUT1 as close to output capacitor as possible to sense output voltage. This feature also provides the path to discharge the output through an internal 900 resistor when disabled. The pull-down feature is programmed through the PULLD[x] register.         30       VSLT       POR Selection Threshold (Input): A high on this pin sets the PORUP and PORDN registers to their upper threshold limits and a low to their lower threshold limits. Do not leave floating.         31       AVIN       Analog Voltage Supply (Input): The start-up sequence begins as soon as the AVIN pin voltage falls below the lower threshold limit. A 2.2µF ceramic capacitor from the AVIN pin voltage falls below the lower threshold limit. A 2.2µF ceramic capacitor from the AVIN pin voltage falls below the lower threshold limit. A 2.2µF ceramic capacitor from the AVIN pin voltage falls below the lower threshold limit. A 2.2µF ceramic capacitor from the AVIN pin voltage falls below the lower threshold ECS UVL) upper threshold. The output that is pulled high when all the regulator power good flags are high. If an output falls below the power good threshold or a thermal fault occurs, the global power good flags are high. If an output falls below the power good threshold or a thermal fault occurs, the global power good flags are high. If an output falls below the po	26	PVIN1	MOSFET. An input capacitor between PVIN1 and the power ground PGND1 pin is required and to be
28       PGND1       connects to the source of the internal low-side N-Channel MOSFET, the negative terminals of input capacitors, and the negative terminals of output capacitors.         29       OUT1       Output Voltage Sense 1 (Input): This pin is used to sense the output voltage remotely. Connect OUT1 as close to output capacitor as possible to sense output voltage. This feature also provides the path to discharge the output through an internal 90Ω resistor when disabled. The pull-down feature is programmed through the PULLD[x] register.         30       VSLT       POR Selection Threshold (Input): A high on this pin sets the PORUP and PORDN registers to their upper threshold limits and a low to their lower threshold limits. Do not leave floating.         31       AVIN       Analog Voltage Supply (Input): The start-up sequence begins as soon as the AVIN pin voltage rises above the IC's UVLO upper threshold. The outputs do not turn off until AVIN pin voltage falls below the lower threshold limit. A 2.2µF ceramic capacitor from the AVIN pin to AGND pin must be placed next to the IC.         32       AGND       Analog Ground: Internal signal ground for all low power circuits. Connect directly to the layer 2 ground plane. Layer 2 is the point where all the PGNDs and AGND are connected. Do not connect PGND and AGND together on the top layer.         33       NC       No Connect. Must be left floating.         34       NC       No Connect. Must be left floating.         35       PG       Global Power Good (Output). This is an open drain output that is pulled high when all the regulator power good flags are high. If an output falls below the power good flags are	27	SW1	
29OUT1as close to output capacitor as possible to sense output voltage. This feature also provides the path to discharge the output through an internal 900 resistor when disabled. The pull-down feature is programmed through the PULLD[x] register.30VSLTPOR Selection Threshold (Input): A high on this pin sets the PORUP and PORDN registers to their upper threshold limits and a low to their lower threshold limits. Do not leave floating.31AVINAnalog Voltage Supply (Input): The start-up sequence begins as soon as the AVIN pin voltage falls below the lower threshold limit. A 2.2µF ceramic capacitor from the AVIN pin voltage falls below the lower threshold limit. A 2.2µF ceramic capacitor from the AVIN pin voltage falls below the lower threshold limit. A 2.2µF ceramic capacitor from the AVIN pin voltage falls below the lower threshold limit. A 2.2µF ceramic capacitor from the AVIN pin voltage falls below the lower threshold limit. A 2.2µF ceramic capacitor from the AVIN pin voltage falls below the lower threshold limit. A 2.2µF ceramic capacitor from the AVIN pin voltage falls below the lower threshold limit. A 2.2µF ceramic capacitor from the AVIN pin voltage falls below the lower threshold limit. A 2.2µF ceramic capacitor from the AVIN pin voltage falls below the lower threshold limit. A 2.2µF ceramic capacitor from the AVIN pin voltage falls below the lower threshold limit. A 2.2µF ceramic capacitor from the AVIN pin voltage falls below the lower threshold limit. A 2.2µF ceramic capacitor from the AVIN pin voltage falls below the lower threshold limit. A 2.2µF ceramic capacitor from the AVIN pin voltage falls below the lower to to he IC.32AGNDAlatog Ground: Internal signal ground for all low power circuits. Connect directly to the layer 2 ground plane. Layer 2 is the point where all the PGNDs and AGND are conn	28	PGND1	connects to the source of the internal low-side N-Channel MOSFET, the negative terminals of input
30VSL1upper threshold limits and a low to their lower threshold limits. Do not leave floating.31AVINAnalog Voltage Supply (Input): The start-up sequence begins as soon as the AVIN pin voltage rises above the IC's UVLO upper threshold. The outputs do not turn off until AVIN pin voltage falls below the lower threshold limit. A 2.2µF ceramic capacitor from the AVIN pin to AGND pin must be placed next to the IC.32AGNDAnalog Ground: Internal signal ground for all low power circuits. Connect directly to the layer 2 ground plane. Layer 2 is the point where all the PGNDs and AGND are connected. Do not connect PGND and AGND together on the top layer.33NCNo Connect. Must be left floating.34NCNo Connect. Must be left floating.35PGGlobal Power Good (Output): This is an open drain output that is pulled high when all the regulator power good flags are high. If an output falls below the power good threshold or a thermal fault occurs, the global power good flag is pulled low. There is a falling edge de-glitch time of 50µs to prevent false triggering on output voltage transients. A power good mask feature programmed through the PGOD_MASK[x] registers can be used to ignore a power good fault. When masked an individual power good fault will not cause the global power good output to de-assert. Do not connect the power good pull-up resistor to a voltage higher than AV <sub>IN</sub> .36PGND2Power Ground 2: The power ground for the synchronous buck converter power stage. The PGND pin connects to the source of the internal low-side N-Channel MOSFET, the negative terminals of input capacitors, and the negative terminals of output capacitors.	29	OUT1	as close to output capacitor as possible to sense output voltage. This feature also provides the path to discharge the output through an internal $90\Omega$ resistor when disabled. The pull-down feature is
31AVINabove the IC's UVLO upper threshold. The outputs do not turn off until AVIN pin voltage falls below the lower threshold limit. A 2.2µF ceramic capacitor from the AVIN pin to AGND pin must be placed next to the IC.32AGNDAnalog Ground: Internal signal ground for all low power circuits. Connect directly to the layer 2 ground plane. Layer 2 is the point where all the PGNDs and AGND are connected. Do not connect PGND and AGND together on the top layer.33NCNo Connect. Must be left floating.34NCNo Connect. Must be left floating.35PGGlobal Power Good (Output): This is an open drain output that is pulled high when all the regulator power good flags are high. If an output falls below the power good threshold or a thermal fault occurs, the global power good flag is pulled low. There is a falling edge de-glitch time of 50µs to prevent false triggering on output voltage transients. A power good mask feature programmed through the PGODD_MASK[X] registers can be used to ignore a power good fault. When masked an individual power good fault will not cause the global power good output to de-assert. Do not connect the power good pull-up resistor to a voltage higher than AV <sub>IN</sub> .36PGND2Power Ground 2: The power ground for the synchronous buck converter power stage. The PGND pin connects to the source of the internal low-side N-Channel MOSFET, the negative terminals of input capacitors, and the negative terminals of output capacitors.	30	VSLT	
32AGNDplane. Layer 2 is the point where all the PGNDs and AGND are connected. Do not connect PGND and AGND together on the top layer.33NCNo Connect. Must be left floating.34NCNo Connect. Must be left floating.35PGGlobal Power Good (Output): This is an open drain output that is pulled high when all the regulator power good flags are high. If an output falls below the power good threshold or a thermal fault occurs, the global power good flag is pulled low. There is a falling edge de-glitch time of 50µs to prevent false triggering on output voltage transients. A power good mask feature programmed through the PGOOD_MASK[x] registers can be used to ignore a power good fault. When masked an individual power good fault will not cause the global power good output to de-assert. Do not connect the power good pull-up resistor to a voltage higher than AV <sub>IN</sub> .36PGND2Power Ground 2: The power ground for the synchronous buck converter power stage. The PGND pin capacitors, and the negative terminals of output capacitors.	31	AVIN	above the IC's UVLO upper threshold. The outputs do not turn off until AVIN pin voltage falls below the lower threshold limit. A $2.2\mu$ F ceramic capacitor from the AVIN pin to AGND pin must be placed
34       NC       No Connect. Must be left floating.         35       PG       Global Power Good (Output): This is an open drain output that is pulled high when all the regulator power good flags are high. If an output falls below the power good threshold or a thermal fault occurs, the global power good flag is pulled low. There is a falling edge de-glitch time of 50µs to prevent false triggering on output voltage transients. A power good mask feature programmed through the PGOOD_MASK[x] registers can be used to ignore a power good fault. When masked an individual power good fault will not cause the global power good output to de-assert. Do not connect the power good pull-up resistor to a voltage higher than AV <sub>IN</sub> .         36       PGND2       Power Ground 2: The power ground for the synchronous buck converter power stage. The PGND pin connects to the source of the internal low-side N-Channel MOSFET, the negative terminals of input capacitors, and the negative terminals of output capacitors.	32	AGND	plane. Layer 2 is the point where all the PGNDs and AGND are connected. Do not connect PGND
35PGGlobal Power Good (Output): This is an open drain output that is pulled high when all the regulator power good flags are high. If an output falls below the power good threshold or a thermal fault occurs, the global power good flag is pulled low. There is a falling edge de-glitch time of 50µs to prevent false triggering on output voltage transients. A power good mask feature programmed through the PGOOD_MASK[x] registers can be used to ignore a power good fault. When masked an individual power good fault will not cause the global power good output to de-assert. Do not connect the power good pull-up resistor to a voltage higher than AV <sub>IN</sub> .36PGND2Power Ground 2: The power ground for the synchronous buck converter power stage. The PGND pin connects to the source of the internal low-side N-Channel MOSFET, the negative terminals of input capacitors, and the negative terminals of output capacitors.	33	NC	No Connect. Must be left floating.
35PGpower good flags are high. If an output falls below the power good threshold or a thermal fault occurs, the global power good flag is pulled low. There is a falling edge de-glitch time of 50µs to prevent false triggering on output voltage transients. A power good mask feature programmed through the PGOOD_MASK[x] registers can be used to ignore a power good fault. When masked an individual power good fault will not cause the global power good output to de-assert. Do not connect the power good pull-up resistor to a voltage higher than AVIN.36PGND2Power Ground 2: The power ground for the synchronous buck converter power stage. The PGND pin connects to the source of the internal low-side N-Channel MOSFET, the negative terminals of input capacitors, and the negative terminals of output capacitors.	34	NC	No Connect. Must be left floating.
36 PGND2 connects to the source of the internal low-side N-Channel MOSFET, the negative terminals of input capacitors, and the negative terminals of output capacitors.	35	PG	power good flags are high. If an output falls below the power good threshold or a thermal fault occurs, the global power good flag is pulled low. There is a falling edge de-glitch time of 50µs to prevent false triggering on output voltage transients. A power good mask feature programmed through the PGOOD_MASK[x] registers can be used to ignore a power good fault. When masked an individual power good fault will not cause the global power good output to de-assert. Do not connect the power
EP ePad Exposed Pad: Must be connected to the GND plane for full output power to be realized.	36	PGND2	connects to the source of the internal low-side N-Channel MOSFET, the negative terminals of input
	EP	ePad	Exposed Pad: Must be connected to the GND plane for full output power to be realized.

### Absolute Maximum Ratings<sup>(3)</sup>

Supply Voltages (PV <sub>IN[1-6]</sub> )	0.3V to 6V
Analog Supply Voltage (AV <sub>IN</sub> )	0.3V to 6V
Buck Output Voltages (V <sub>OUT[1-5]</sub> )	
Boost Output Voltage (V <sub>OUT6</sub> )	0.3V to 20V
Buck Switch Voltages (V <sub>SW[1-5]</sub> )	
Boost Switch Voltage (V <sub>SW6</sub> ).	0.3V to 20V
Power Good Voltage (V <sub>PG</sub> )	
Power-On Reset Output (V <sub>POR</sub> )	0.3V to 6V
POR Threshold Voltage (V <sub>VSLT</sub> )	0.3V to 6V
Standby Voltage (V <sub>STBY</sub> )	0.3V to 6V
I <sup>2</sup> C IO (V <sub>SDA</sub> , V <sub>SCL</sub> )	0.3V to AV <sub>IN</sub>
AGND to PGND[1-6]	0.3V to 0.3V
Ambient Storage Temperature (Ts)	40°C to +150°C
ESD HBM Rating <sup>(6)</sup>	2kV
ESD MM Rating	

## **Operating Ratings**<sup>(4)</sup>

Input Voltage (PV <sub>IN[1-6]</sub> ) Analog Input Voltage (AV <sub>IN</sub> )	
Buck Output Voltage Range (V <sub>OUT[1-5]</sub> )	
Boost Output Voltage Range (V <sub>OUT[1-5]</sub> )	
Power Good Voltage (V <sub>PG</sub> )	
Power-On Reset Output (V <sub>PG</sub> )	
POR Threshold Voltage (V <sub>VSLT</sub> )	
Standby Voltage (V <sub>STBY</sub> )	
$I^2C IO (V_{SDA}, V_{SCL})$	
Junction Temperature $(T_{,j})^{(5)}$ 40°	
Junction Thermal Resistance	0 10 1 20 0
4.5mm × 4.5mm FQFN-36 (θ <sub>JA</sub> )	30°C/W

# Electrical Characteristics<sup>(7)</sup>

 $V_{IN} = AV_{IN} = PV_{IN(1-6)} = 5.0V$ ;  $V_{OUT1} = 1.8V$ ;  $V_{OUT2} = 1.1V$ ;  $V_{OUT3} = 1.8V$ ;  $V_{OUT4} = 1.05V$ ;  $V_{OUT5} = 1.25V$ ;  $V_{OUT6} = 12V$  (refer to the *Evaluation Board Schematic* for component values). T<sub>A</sub> = 25°C, unless otherwise noted. **Bold** values indicate  $-40°C \le T_J \le +125°C$ .

Parameter	Conditions	Min.	Тур.	Max.	Unit
Input Supply (VIN)					
Input Voltage Range (AV <sub>IN</sub> , PV <sub>IN[1-6]</sub> )		2.4		5.5	V
Operating Quiescent Current into AV <sub>IN</sub> <sup>(8, 9)</sup>	V <sub>IN</sub> = 5.0V; I <sub>OUT</sub> = 0A		200	240	μA
Operating Quiescent Current into PV <sub>IN</sub> <sup>(8)</sup>	V <sub>IN</sub> = 5.0V; I <sub>OUT</sub> = 0A		0.3	1	μA
Undervoltage Lockout Threshold	AV <sub>IN</sub> Rising	2.15	2.25	2.35	V
Undervoltage Lockout Hysteresis			150		mV
Standby Input (STBY)					
Logic Level High		1.2			V
Logic Level Low				0.4	V
Bias Current into Pin	V <sub>STBY</sub> = V <sub>IN</sub>			200	nA
Bias Current out of Pin	$V_{STBY} = 0V$			200	nA
Rising/Falling Edge Reset Deglitch			100		μs

#### Notes:

3. Absolute maximum ratings indicate limits beyond which damage to the component may occur.

4. The device is not guaranteed to function outside its operating rating.

5. The maximum allowable power dissipation is a function of the maximum junction temperature,  $T_{J(Max)}$ , the junction-to-ambient thermal resistance,  $\theta_{JA}$ , and the ambient temperature,  $T_A$ . The maximum allowable power dissipation will result in excessive die temperature, and the regulator will go into thermal shutdown.

 $6. \quad \text{Devices are ESD sensitive. Handling precautions recommended. Human body model, } 1.5 \text{k}\Omega \text{ in series with } 100 \text{pF.}$ 

7. Specification for packaged product only.

8. Tested in a non-switching configuration.

9. When all outputs are configured to the minimum programmable voltage.

 $V_{IN} = AV_{IN} = PV_{IN(1-6)} = 5.0V; V_{OUT1} = 1.8V; V_{OUT2} = 1.1V; V_{OUT3} = 1.8V; V_{OUT4} = 1.05V; V_{OUT5} = 1.25V; V_{OUT6} = 12V \text{ (refer to the Evaluation Board Schematic} for component values). T_A = 25°C, unless otherwise noted.$ **Bold** $values indicate <math>-40°C \le T_J \le +125°C$ .

Parameter	Conditions	Min.	Тур.	Max.	Unit
POR Threshold Input (VSLT)					-
Logic Level High		1.2			V
Logic Level Low				0.4	V
Bias Current Into Pin	$V_{VSLT} = V_{IN}$			200	nA
Bias Current Out of Pin	$V_{VSLT} = 0V$			200	nA
Power-On-Reset (POR) Comparator					-
POR Upper Comparator Range	$AV_{IN}$ Rising, $V_{VSLT} = 0V$	2.646	2.7	2.754	V
POR Lower Comparator Range	$AV_{IN}$ Falling, $V_{VSLT} = 0V$	2.548	2.6	2.652	V
POR Upper Comparator Range	$AV_{IN}$ Rising, $V_{VSLT} = V_{IN}$	3.626	3.7	3.774	V
POR Lower Comparator Range	$AV_{IN}$ Falling, $V_{VSLT} = V_{IN}$	3.528	3.6	3.672	V
Power Reset Output (POR) and Time	r				
POR Delay		18	20	22	ms
POR Deglitch Delay	AV <sub>IN</sub> Falling		50		μs
POR Output Low Voltage	I <sub>POR</sub> = 10mA (sinking)		75	400	mV
POR Leakage Current	V <sub>POR</sub> = 5.5V			200	nA
Global Power Good Output (PG)					-
Buck Power Good Threshold Voltage	V <sub>OUT[1-5]</sub> Rising	87	91	95	%V <sub>OUT</sub>
Buck Hysteresis <sup>(10)</sup>	V <sub>OUT[1-5]</sub> Falling		4		%V <sub>OUT</sub>
Boost Power Good Threshold Voltage	V <sub>OUT[6]</sub> Rising	87	91	95	%V <sub>OUT</sub>
Boost Hysteresis <sup>(10)</sup>	V <sub>OUT[6]</sub> Falling		380		mV
Power Good Output Low Voltage	I <sub>PG</sub> = 10mA (sinking)		75	400	mV
Power Good Leakage Current	V <sub>PG</sub> = 5.5V		0.01	200	nA
Power Good De-Glitch Delay	V <sub>OUT[1-6]</sub> Falling		100		μs
Output Sequencing Delay <sup>(10)</sup>		0.96	1	1.04	ms
Thermal Protection	-		<b>_</b>		-
Thermal Shutdown	T <sub>J</sub> Rising		160		°C
Thermal Hysteresis			20		°C

Note:

10. Guaranteed by design.

 $V_{\text{IN}} = AV_{\text{IN}} = PV_{\text{IN}(1-6)} = 5.0V; V_{\text{OUT1}} = 1.8V; V_{\text{OUT2}} = 1.1V; V_{\text{OUT3}} = 1.8V; V_{\text{OUT4}} = 1.05V; V_{\text{OUT5}} = 1.25V; V_{\text{OUT6}} = 12V \text{ (refer to the$ *Evaluation Board Schematic*for component values). T<sub>A</sub> = 25°C, unless otherwise noted.**Bold** $values indicate <math>-40^{\circ}C \le T_{\text{J}} \le +125^{\circ}C$ .

Parameter	Conditions	Min.	Тур.	Max.	Unit
Synchronous Buck (V <sub>OUT1</sub> - V <sub>OUT5</sub> )					
Buck Output Voltage Accuracy (OUT	[1-5])				
Typical Output Voltage 1 Accuracy <sup>(11)</sup>	Includes Load, Line, and Reference	-1.5%		1.5%	%
Typical Output Voltage 2 Accuracy <sup>(11)</sup>	Includes Load, Line, and Reference	-1.5%		1.5%	%
Typical Output Voltage 3 Accuracy <sup>(11)</sup>	Includes Load, Line, and Reference	-1.5%		1.5%	%
Typical Output Voltage 4 Accuracy <sup>(11)</sup>	Includes Load, Line, and Reference	-1.5%		1.5%	%
Typical Output Voltage 5 Accuracy <sup>(11)</sup>	Includes Load, Line, and Reference	-1.5%		1.5%	%
Output Voltage 1 Accuracy <sup>(11)</sup>		-1%		1%	%
Output Voltage 2 Accuracy <sup>(11)</sup>		-1%		1%	%
Output Voltage 3 Accuracy <sup>(11)</sup>		-1%		1%	%
Output Voltage 4 Accuracy <sup>(11)</sup>		-1%		1%	%
Output Voltage 5 Accuracy <sup>(11)</sup>		-1%		1%	%
Load Regulation	I <sub>OUT</sub> = 10mA to I <sub>OUT(MAX)</sub>		0.1		%
Line Regulation	$V_{IN} = 3.3V$ to 5.0V		0.05		%
Buck Soft-Start					
Soft-Start (1-5) LSB <sup>(10, 12)</sup>		3.84	4	4.16	µs/step
Buck Internal MOSFETs	•	ł			
High-Side On-Resistance	V <sub>IN</sub> = 3.3V; I <sub>SW[1-5]</sub> = 200mA		54		mΩ
High-Side On-Resistance	V <sub>IN</sub> = 5.0V; I <sub>SW[1-5]</sub> = 200mA		40		mΩ
Low-Side On-Resistance $V_{IN} = 3.3V; I_{SW[1-5]} = -200 \text{mA}$			37		mΩ
Low-Side On-Resistance	V <sub>IN</sub> = 5.0V; I <sub>SW[1-5]</sub> = -200mA		30		mΩ
Output Pull-Down Resistance	V <sub>SW[1-5]</sub> = 0V	75	90	200	Ω
Buck Controller Timing	•	<u>.</u>	<u> </u>		•
Fixed On-Time <sup>(13)</sup>	V <sub>IN</sub> = 3.3; V <sub>OUT</sub> = 1.0V; I <sub>OUT</sub> = 1.0A		220		ns
Minimum OFF-Time			80		ns

Note:

11. Not tested in a closed loop configuration.

12. The soft-start time is calculated using the following equation:  $t_{softstart} = [(V_{OUT_PROGRAM} - 0.15)/0.05 + 1) \times t_{RAMP}$ .

13. Buck frequency is calculated using the following equation  $f_{SW} = (V_{OUT}/V_{IN}) \times (1/t_{ON})$ .

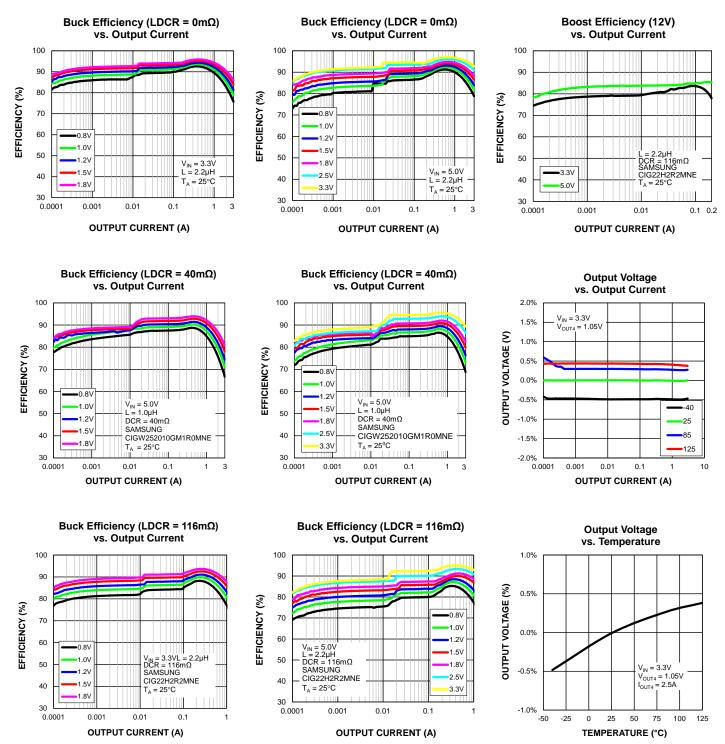
 $V_{IN} = AV_{IN} = PV_{IN(1-6)} = 5.0V; V_{OUT1} = 1.8V; V_{OUT2} = 1.1V; V_{OUT3} = 1.8V; V_{OUT4} = 1.05V; V_{OUT5} = 1.25V; V_{OUT6} = 12V \text{ (refer to the Evaluation Board Schematic for component values)}. T_A = 25^{\circ}C, unless otherwise noted. Bold values indicate -40^{\circ}C \leq T_J \leq +125^{\circ}C.$ 

Parameter	Conditions	Min.	Тур.	Max.	Unit
Buck Current Limit (OUT1-OUT5)					
Buck 1 Current Limit Threshold	See Table 3 for IPROG Settings	3.075	4.1	5.125	А
Buck 2 Current Limit Threshold	See Table 3 for IPROG Settings	3.075	4.1	5.125	А
Buck 3 Current Limit Threshold	See Table 3 for I <sub>PROG</sub> Settings	3.075	4.1	5.125	Α
Buck 4 Current Limit Threshold	See Table 3 for I <sub>PROG</sub> Settings	4.88	6.1	7.32	Α
Buck 5 Current Limit Threshold	See Table 3 for IPROG Settings	3.075	4.1	5.125	Α
Gross High-Side Current Limit [1-5]	With Respect to Buck [x] Current Limit		150		%
Zero Cross Threshold	Zero crossing detector		0		mV
Boost (V <sub>OUT6</sub> )					
Boost Output Voltage (V <sub>OUT6</sub> )					
Typical Output Voltage Accuracy <sup>(11)</sup>	Includes Load, Line, and Reference	-1.5%		1.5%	%
Output Voltage Accuracy <sup>(11)</sup>		-1%		1%	%
Load Regulation	I <sub>OUT6</sub> = 1.0mA to 200mA		0.2		%
Line Regulation	$V_{IN} = 2.4V$ to 5.5V; $I_{OUT6} = 10mA$		0.2		%
V <sub>OUT6</sub> Discharge Current	$V_{IN} = 3.3V; V_{OUT6} = 12V$	111	148	185	mA
Boost Soft-Start Step Duration					
Soft-Start 6 LSB <sup>(10, 12)</sup>		3.84	4	4.16	µs/step
Boost Internal MOSFETs					
Low-Side On-Resistance	$V_{IN} = 3.3V; I_{SW1} = -100mA$		160		mΩ
Low-Side On-Resistance	$V_{IN} = 5.0V; I_{SW1} = -100mA$		140		mΩ
Boost Disconnect MOSFETs					-
Disconnect Switch On-Resistance	I <sub>PVIN60</sub> = 100mA; V <sub>IN</sub> = 3.3V		90		mΩ
Disconnect Switch Current Limit			5		А
Boost Switching Frequency		•			
Switching Frequency (PWM Mode)		1.92	2	2.08	MHz
inimum Duty Cycle		35	40	45	%
Maximum Duty Cycle		80	85	90	%
Boost Current Limit		1			
NMOS Current-Limit Threshold			2.24		А

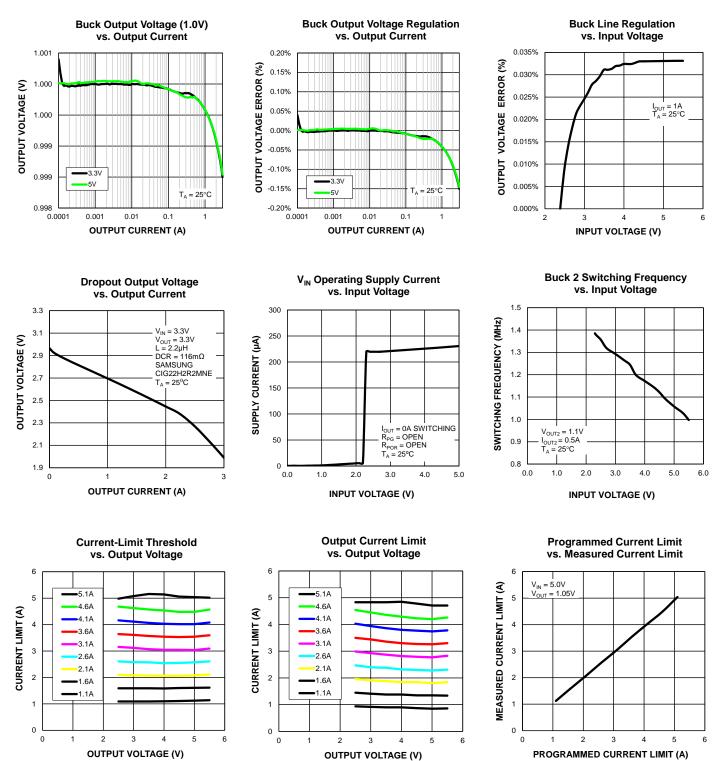
 $V_{IN} = AV_{IN} = PV_{IN(1-6)} = 5.0V; V_{OUT1} = 1.8V; V_{OUT2} = 1.1V; V_{OUT3} = 1.8V; V_{OUT4} = 1.05V; V_{OUT5} = 1.25V; V_{OUT6} = 12V \text{ (refer to the Evaluation Board Schematic for component values).} T_A = 25^{\circ}C, unless otherwise noted. Bold values indicate -40^{\circ}C \le T_J \le +125^{\circ}C.$ 

Parameter	Conditions	Min.	Тур.	Max.	Unit	
I <sup>2</sup> C Interface	·	•			•	
I <sup>2</sup> C Interface (SCL, SDA)						
Low Level Input Voltage				0.4	V	
High Level Input Voltage		1.2			V	
High Level Input Current		-200	0.01	200	nA	
Low Level Input Current		-200	0.01	200	nA	
SDA Pull-Down Resistance			20		Ω	
SDA Logic 0 Output Voltage	I <sub>SDA</sub> = 3mA			0.4	V	
CLK, DATA Pin Capacitance			0.7		pF	
I <sup>2</sup> C Interface Timing <sup>(10)</sup>	•	·				
	Standard Mode			100		
SCL Clock Frequency	Fast Mode			400	kHz	
	High-Speed Mode <sup>(10)</sup>			3.4	MHz	

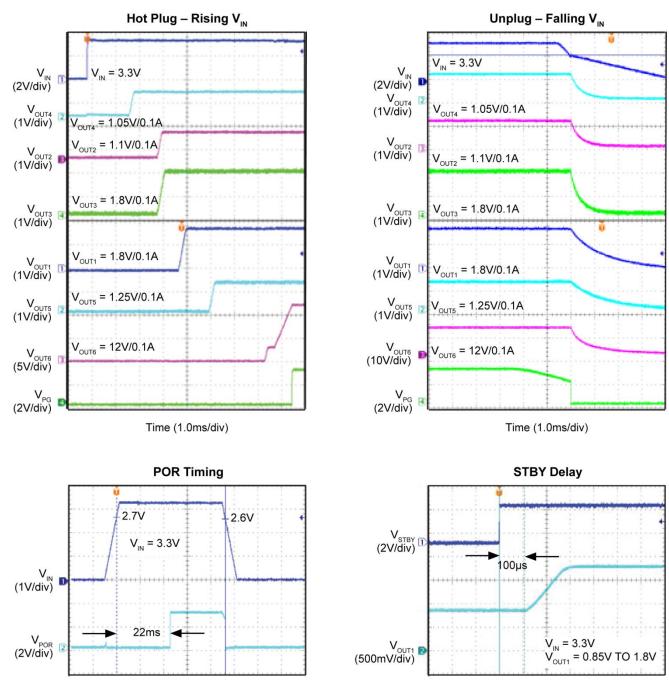
## **Typical Characteristics**



## **Typical Characteristics (Continued)**

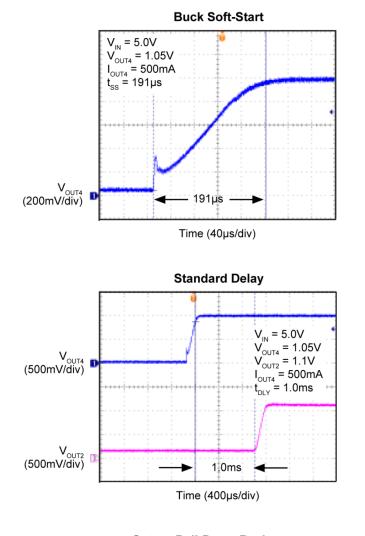


### **Functional Characteristics**

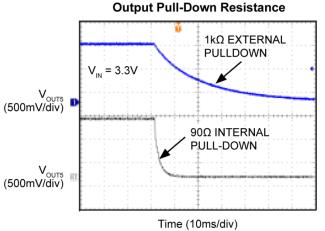


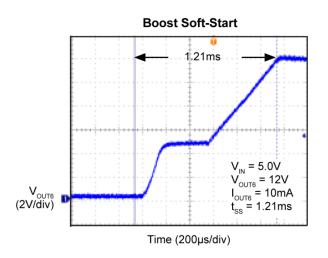
Time (100µs/div)

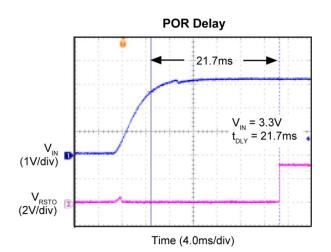
Time (10ms/div)

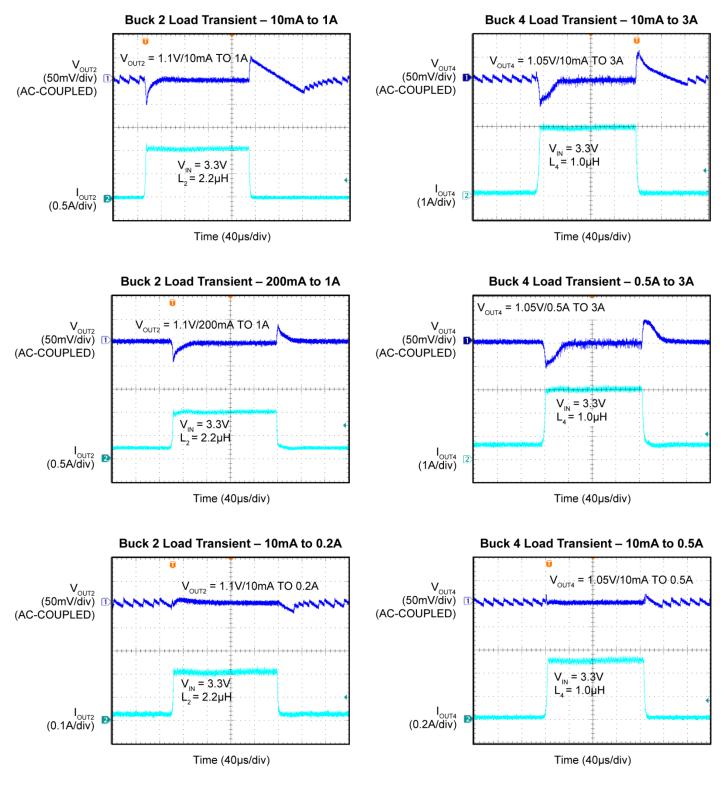


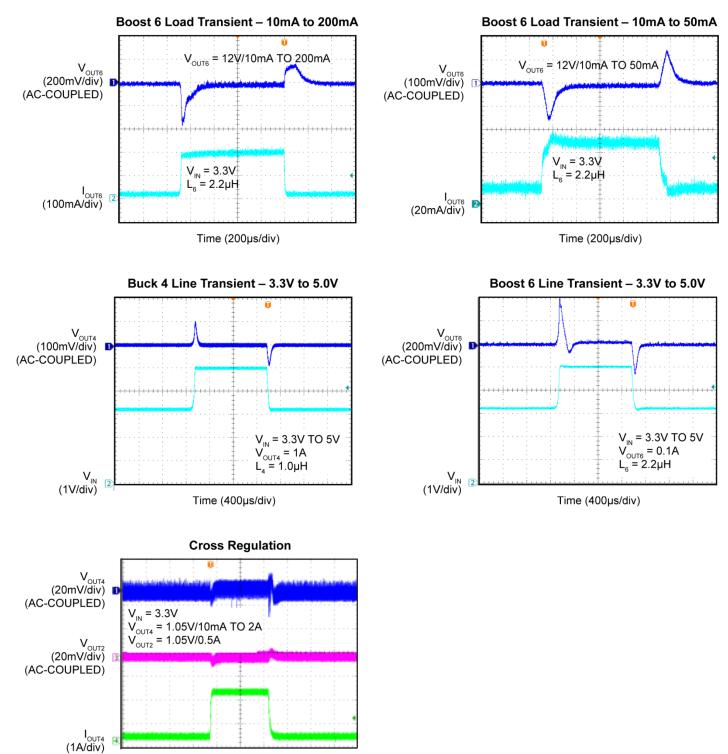




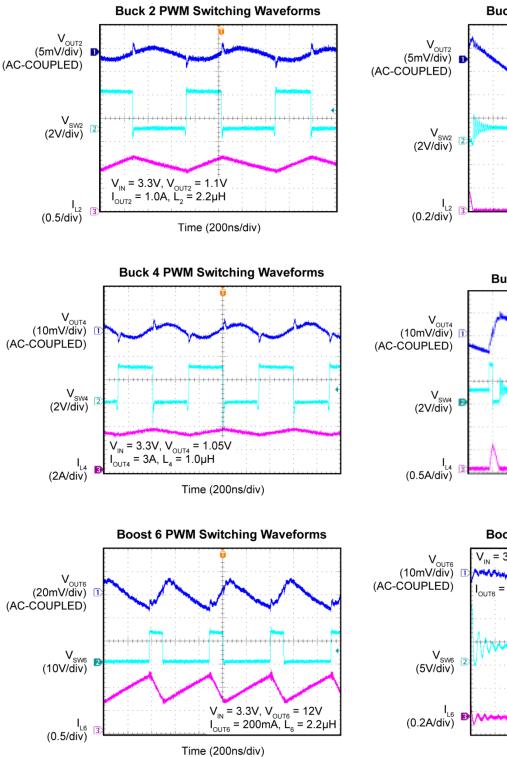




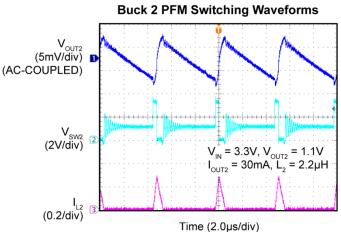




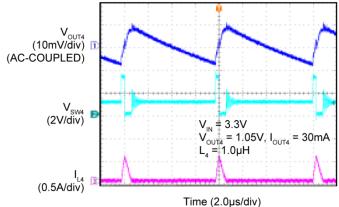
Time (200µs/div)

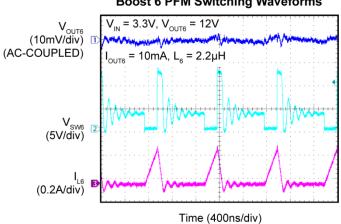


MIC7400

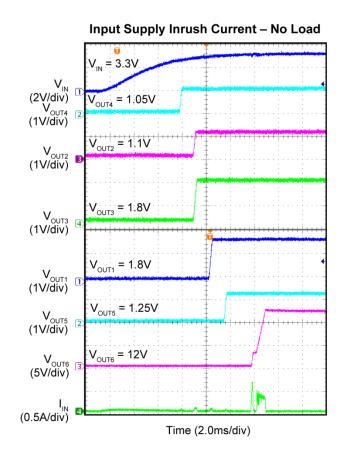


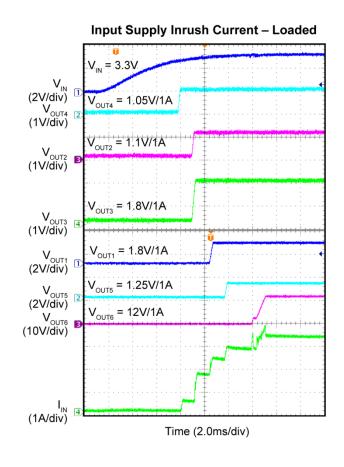
**Buck 4 PFM Switching Waveforms** 

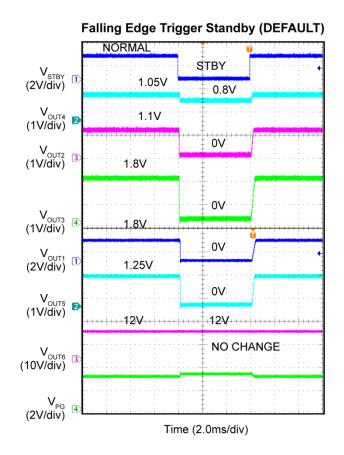


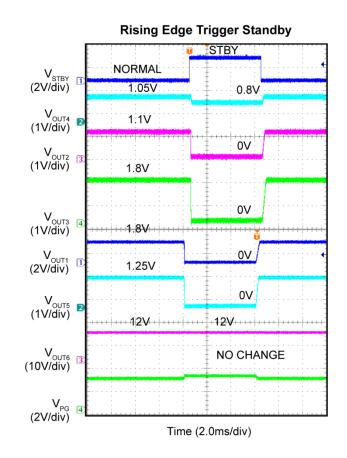


### Boost 6 PFM Switching Waveforms

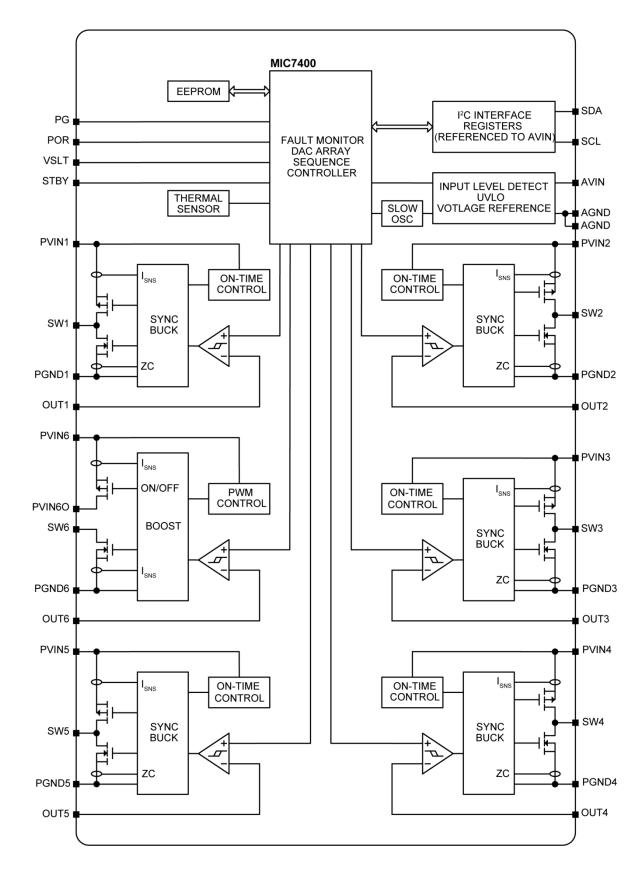








## MIC7400 Block Diagram



## **Functional Description**

The MIC7400 is one of the industry's most-advanced PMIC designed for solid state drives (SSD) on the market today. It is a multi-channel solution which offers software configurable soft-start, sequencing, and digital voltage control (DVC) that minimizes PC board area. These features usually require a pin for programming. However, this approach makes the IC larger by increasing pin count, and also increases BOM cost due to the external components.

The following is a complete list of programmable features:

- Buck output voltage (0.8V 3.3V/50mV steps)
- Boost output voltage (7.0V 14V/ 200mV steps)
- Power-on-reset (2.25V 4.25V/50mV steps)
- Power-on-reset delay (5ms 160ms/5ms steps)
- Power-up sequencing (6 time slots)
- Power-up sequencing delay (0ms 7ms/1ms steps)
- Soft-start (4µs 1024µs per step)
- Buck current limit threshold
  - (1.1A to 6.1A/0.5A steps)
- Boost current limit threshold
  - (1.76A to 2.6A/0.12A steps)
- Boost pull-down (37mA to 148mA/37mA steps)
- Buck pull-down (90Ω)
- Buck standby output voltage programmable
- Boost standby output voltage programmable
- Global power good masking

These features give the system designer the flexibility to customize the MIC7400 for their application. For example,  $V_{OUT1}$  current limit can be programmed to 4.1A and  $V_{OUT2}$  can be set to 1.1A. These outputs can be programmed to come up at the same time or 2.0ms apart. In addition, in power-saving standby mode, the outputs can either be turned off or programmed to a lower voltage. With this programmability the MIC7400 can be used in multiple platforms.

The MIC7400 buck regulators are adaptive on-time synchronous step-down DC-to-DC regulators. They are designed to operate over a wide input voltage range from 2.4V to 5.5V and provide a regulated output voltage at up to 3.0A of output current. An adaptive on-time control scheme is employed to obtain a constant switching frequency and to simplify the control compensation. The device includes an internal soft-start function which reduces the power supply input surge current at start-up by controlling the output voltage rise time.

The MIC7400 has a current-mode boost regulator that can deliver up to 200mA of output current and only consumes  $70\mu$ A of quiescent current. The 2.0MHz switching frequency allows small chip inductors to be used. Programmable overcurrent sensing protects the boost from overloads and an output disconnect switch opens to protect against a short-circuit condition. Softstart is also programmable and controls both the rising and falling output.

#### Programmable Buck Soft-Start Control

The MIC7400 soft-start feature forces the output voltage to rise gradually, which limits the inrush current during start-up. A slower output rise time will draw a lower input surge current. The soft-start time is based on the least significant bit (LSB) of an internal DAC and the speed of the ramp rate, as shown in Figure 1. This illustrates the soft-start waveform for all five synchronous buck converters. The initial step starts at 150mV and each subsequent step is 50mV.

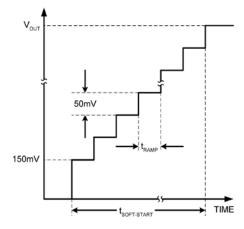


Figure 1. Buck Soft-Start

The output ramp rate ( $t_{RAMP}$ ) is set by the soft-start registers. Each output ramp rate can be individually set from 4µs to 1024µs, see Table 1 for details.

The soft-start time  $t_{SS}$  can be calculated by Equation 1:

$$t_{SS} = \left(\frac{V_{OUT} - 0.15V}{50mV}\right) \times t_{RAMP}$$
 Eq. 1

Where:

 $t_{SS}$  = Output rise time V<sub>OUT</sub> = Output voltage  $t_{RAMP}$  = Output dwell time

For example:

$$t_{SS} = \left(\frac{1.8V - 0.15V}{50mV}\right) \times 8\mu s$$
$$t_{SS} = 264\mu s$$

Where:

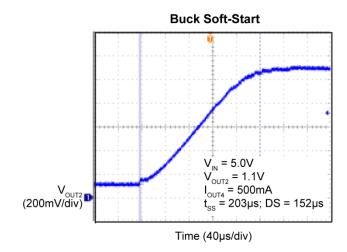
 $V_{OUT} = 1.8V$ 

 $t_{RAMP} = 8.0 \mu s$ 

	V <sub>оит</sub> (V)	t <sub>RAMP</sub> (μs)	t <sub>ss</sub> (µs)
V <sub>OUT1</sub>	1.8	8	264
V <sub>OUT2</sub>	1.1	8	152
V <sub>OUT3</sub>	1.8	8	264
V <sub>OUT4</sub>	1.05	8	144
V <sub>OUT5</sub>	1.25	8	176

 Table 1. Buck Outputs Default Soft-Start Time (DEFAULT)

Figure 2 shows the output of Buck 1 ramping up cleanly, starting from 0.15V to its final 1.1V value.





### Buck Digital Voltage Control (DVC)

The output voltage has a 6-bit control DAC that can be programmed from 0.8V to 3.3V in 50mV increments. If the output is programmed to a higher voltage, then the output ramps up, as shown in Figure 3.

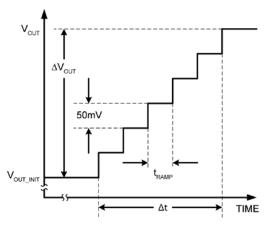


Figure 3. Buck DVC Control Ramp

The ramp time is determined by Equation 2:

$$\Delta t = \left(\frac{V_{OUT} - V_{OUT}_{INIT}}{50 \text{mV}}\right) \times t_{RAMP}$$
 Eq. 2

Where:

V<sub>OUT INIT</sub> = Initial output voltage

 $V_{OUT}$  = Final output voltage

 $t_{RAMP}$  = Output dwell time

When the regulator is set in stand-by mode or programmed to a lower voltage, then the output voltage ramps down at a rate determined by the output ramp rate ( $t_{RAMP}$ ), the output capacitance and the external load. Small loads result in slow output voltage decay and heavy loads cause the decay to be controlled by the DAC ramp rate.

In Figure 4,  $V_{OUT1}$  is switched to stand-by mode with an I<sup>2</sup>C command and then switched back to normal mode either by an I<sup>2</sup>C command or a low-to-high transition of the STBY pin. In this case, the rise and fall times are the same due to a 1A load on  $V_{OUT1}$ .

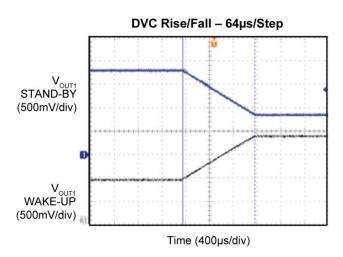
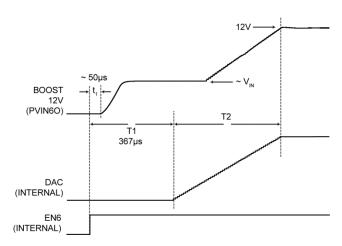


Figure 4. Buck DVC Control Ramp

### Programmable Boost Soft-Start Control

The boost soft-start time is divided into two parts as shown in Figure 5. T1 is a fixed 367µs delay starting from when the internal enable goes high. This delay gives enough time for the disconnect switch to turn on and bring the inductor voltage to  $V_{\rm IN}$  before the boost is turned on. There is a 50µs delay which is controlled by the parasitic capacitance (Cgd) of the disconnect switch before the output starts to rise.

After the T1 period, the DAC output ramp starts, T2. The total soft-start time,  $t_{SS}$ , is the sum of both periods. Figure 6 displays the actual boost soft-start waveform.





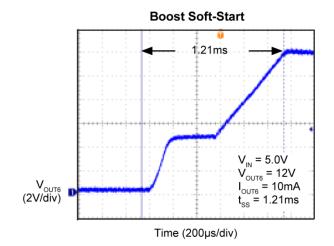


Figure 6. Boost Soft-Start

$$\begin{split} t_{SS} &= T1 + T2 \\ T2 &= \left(\frac{\left(V_{OUT} - 1.4V\right)}{0.2V}\right) \times t_{RAMP} \\ T2 &= \left(\frac{\left(12V - 1.4V\right)}{0.2V}\right) \times 16 \mu s \end{split}$$

Where:

T1 =  $367\mu s$ T2 =  $848\mu s$ t<sub>SS</sub> =  $367\mu s + 848\mu s = 1.215m s$ V<sub>OUT</sub> = Output voltage t<sub>RAMP</sub> = Output dwell time =  $16\mu s$ 

#### **Boost Digital Voltage Control (DVC)**

The boost output control works the same way as the buck, except that the voltage steps are 200mV, see Figure 7. When the boost is programmed to a lower voltage the output ramps down at a rate determined by the output ramp rate ( $t_{RAMP}$ ), the output capacitance and the external load. During both the ramp up and down time, the power good output is blanked and if the power good mask bit is set to "1".

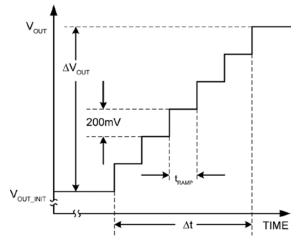


Figure 7. Boost DVC Control Ramp

The ramp time can be computed using Equation 3:

$$\Delta t = \left(\frac{V_{OUT} - V_{OUT\_INIT}}{0.2V}\right) \times t_{RAMP}$$
 Eq. 3

Where:

V<sub>OUT\_INIT</sub> = Initial output voltage

#### Table 2. Boost Output Default Soft-Start Time

	V <sub>out</sub>	t <sub>ramp</sub>	t <sub>ss</sub>
	(V)	(μs)	(ms)
V <sub>OUT6</sub>	12	16	1.215

#### **Buck Current Limit**

The MIC7400 buck regulators have high-side current limiting that can be varied by a 4-bit code. If the regulator remains in current limit for more than seven consecutive PWM cycles, the output is latched off, the over-current status register bit is set to 1, the power-good status register bit is set to 0 and the global power good (PG) output pin is pulled low. An overcurrent fault on one output will not disable the remaining outputs. Table 3 shows the current limit register settings verses output current. The current limit register setting is set at twice the maximum output current.

I <sub>OUT(MAX)</sub>	I <sub>PROG</sub>	BINARY	HEX
0.5A	1.1A	1111	F'h
1.0A	2.1A	1101	D'h
1.5A	3.1A	1011	B'h
2.0A	4.1A	1001	9'h
2.5A	5.1A	0111	7'h
3.0A	6.1A	0101	5'h

#### Table 3. Buck Current Limit Register Settings

The output can be turned back on by recycling the input power or by software control. To clear the overcurrent fault by software control, set the enable register bit to "0" then clear the overcurrent fault by setting the fault register bit to "0". This will clear the over-current and power good status registers. Now the output can be reenabled by setting the enable register bit to "1". During start-up sequencing if Output 1 is still shorted, Outputs 2 through 4 will come up normally. Once an overcurrent condition is sensed, then the fault register is set to "1" and the start-up sequence will stop and no further outputs will be enabled. See Figure 9 for default start-up sequence.

#### **Boost Current Limit**

The boost current limit features cycle-by-cycle protection. The duty cycle is cut immediately once the current limit is hit. When the boost current limit is hit for five consecutive cycles, the FAULT signal is asserted and remains asserted with the boost converter keeping on running until the boost is powered off.

This protects the boost in normal overload conditions, but not in a short-to-ground case. For a short circuit to ground, the boost current limit will not be able to limit the inductor current. This short-circuit condition is sensed by the current in the disconnect switch. When the disconnect switch current limit is hit for four consecutive master clock cycles (2MHz), regardless if the boost is switching or not, both the disconnect switch and boost are latched off automatically and the FAULT signal is asserted.

The output can be turned back on by recycling the input power or by software control. To clear the overcurrent fault by software control, set the enable register bit to "0" then clear the overcurrent fault by setting the fault register bit to "0".

#### **Global Power Good Pin**

The global power-good output indicates that all the outputs are above the 91% limit after the power-up sequence is completed. Once the power-up sequence is complete, the global power good output stays high unless an output falls below its power-good limit, a thermal fault occurs, the input voltage drops below the lower UVLO threshold or an output is turned OFF by setting the enable register bit to "0" unless the PGOOD\_MASK[x] bit is set to "1" (Default).

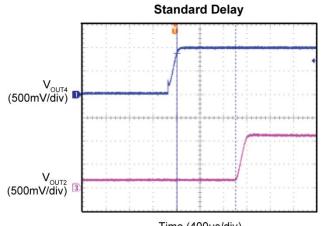
A power-good mask bit can be used to control the global power good output. The power-good mask feature is programmed through the PGOOD\_MASK[x] registers and is used to ignore an individual power-good fault. When masked, PGOOD\_MASK[x] bit is set to "1", an individual power good fault will not cause the global power good output to de-assert.

If all the PGOOD\_MASK[x] bits are set to "1", then the power good output de-asserts as soon as the first output starts to rise. The PGOOD\_MASK[x] bit of the last output must be set to "0" to have the PG output stay low until the last output reaches 91% of its final value.

The global power-good output is an open-drain output. A pull-up resistor can be connected to  $V_{\text{IN}}$  or  $V_{\text{OUT}}$ . Do not connect the pull-up resistor to a voltage higher than  $AV_{\text{IN}}$ .

#### **Standard Delay**

There is a programmable timer that is used to set the standard delay time between each time slot. The timer starts as soon as the previous time slot's output power good goes high. When the delay completes, the regulators assigned to that time slot are enabled, see Figure 8.



Time (400µs/div)

#### Figure 8. Standard Delay Time

#### Power-Up Sequencing

When power is first applied to the MIC7400, all I<sup>2</sup>C registers are loaded with their default values from the EEPROM. There is about a 1.5ms delay before the first regulator is enabled while the MIC7400 goes through the initialization process. The DELAY register's STDEL bits set the delay between powering up each regulator at initial power up.

The sequencing registers allow the outputs to come up in any order. There are six time slots that an output can be configured to power up in. Each time slot can be programmed for up to six regulators to be turned on at once or none at all.

Figure 9 shows an example of this feature.  $V_{OUT4}$  is enabled in time slot 1. After a 1ms delay,  $V_{OUT2}$  and  $V_{OUT3}$ are enable at the same time in time slot 2. The 1ms is the standard delay for all of the outputs and can be programmed from 0ms to 7ms in 1ms. Next,  $V_{OUT1}$  is powered up in time slot 3 and  $V_{OUT5}$  in time slot 4. There are no regulators programmed for time slot 5. Finally,  $V_{OUT6}$  is powered up in time slot 6. The global power good output,  $V_{PG}$ , goes high as soon as the last output reaches 91% of its final value.

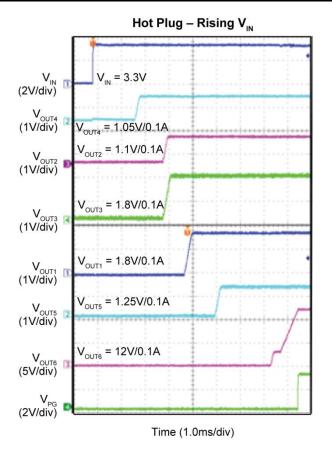


Figure 9. Hot Plug – VIN Rising

#### VSLT Pin

The power-on reset threshold toggles between two different ranges by driving the VSLT pin high or low. The lower range of 2.25V to 3.25V is selected when the VSLT pin is tied to ground. The upper range, 3.25V to 4.25V, is selected when the VSLT pin is tied to  $V_{\rm IN}$ .

#### Programmable Power-on-Reset (POR) Delay

The POR output pin provides the user with a way to let the SOC know that the input power is failing. If the input voltage falls below the power-on reset lower threshold level, the POR output immediately goes low. The lower threshold is set in the PORDN register and the upper threshold uses PORUP register.

The low-to-high POR transition can be delayed from 5ms to 160ms in 5ms increments. This feature can be used to signal the SOC that the power supplies are stable. The PORDEL register sets the delay of the POR pin. The POR delay starts as soon as the AVIN pin voltage rises above the power-on reset upper threshold limit. Figure 10 shows the POR operation.

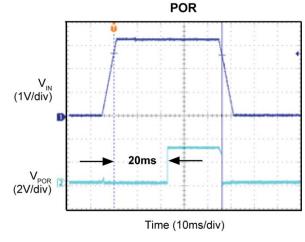


Figure 10. POR

### **Power-Down Sequencing**

When power is removed from  $V_{IN}$ , all the regulators try to maintain the output voltage until the input voltage falls below the UVLO limit of 2.35V as shown in Figure 11.

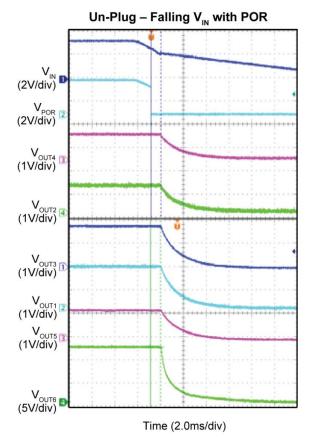


Figure 11. Hot Un-Plug – V<sub>IN</sub> Falling

#### Stand-By Mode

In stand-by mode, efficiency can be improved by lowering the output voltage to the standby mode value or turning an output off completely. There are two registers used for setting the output voltage, normal-mode register and stand-by mode register. The default power-up voltages are set in the normal-mode registers.

An I<sup>2</sup>C write command to the STBY\_CTRL\_REG register or the STBY pin can be used to set the MIC7400 into stand-by mode. Figure 12 shows an I<sup>2</sup>C write command implementation. In stand-by mode, the output can be programmed to a lower voltage or turned completely off. When disabled, the output will be soft-discharged to zero if the PULLD[1-6] register are set to 1. If PULLD[x] = 0 the output drifts to PGND at a rate determined by the load current and output capacitance.

In stand-by, if an output is disabled, the global power good output is not affected when the PGOOD\_MASK[x] is set to logic 1. If the PGOOD\_MASK[x] is set to logic 0, then the global power good flag is pulled low. In Figure 12, all the PGOOD\_MASK[x] bits are set to logic 1.

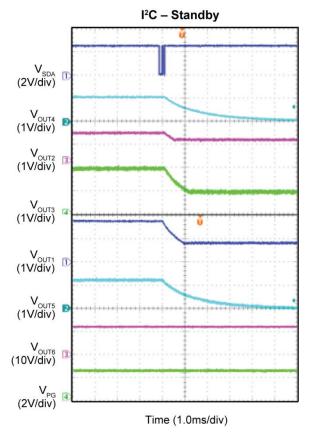


Figure 12. I<sup>2</sup>C Stand-By Mode

#### Resistive Discharge

To ensure a known output condition in stand-by mode, the output is actively discharged to ground if the output is disabled. Setting the buck pull down register field PULLD[1-5] = 1 connects a 90 $\Omega$  pull down resistor from OUT[x] to PGND[x] when the MIC7400 is disabled. If PULLD[x] = 0 the output drifts to PGND at a rate determined by the load current and the output capacitance value. The boost has a programmable pull-down current level from 37mA to 148mA. In Figure 13, the top trace shows the normal pull down and the bottom trace is with the 90 $\Omega$  pull-down.

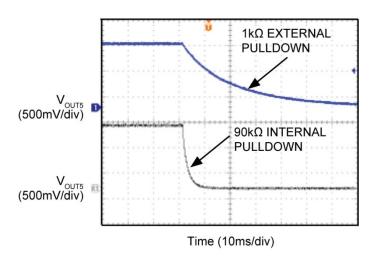


Figure 13. Output Pull-Down Resistance

#### STBY Pin

A pin-selectable STBY input allows the MIC7400 to be placed into standby or normal mode. In standby mode, the individual regulator can be turned on or off or the output voltage can be set to a different value. If the regulators are turned off, standby mode cuts the quiescent current by  $23\mu$ A for each buck regulator and  $70\mu$ A for the boost.

Figure 14 illustrates the STBY pin operation. A low-tohigh transition on the STBY pin switches the output from standby mode to normal mode. There is a 100µs STBY deglitch time to eliminate nuisance tripping then all the regulators are enabled at the same time and ramp up with their programmed ramp rates. A high-to-low transition on the STBY pin switches the output from normal mode to standby mode.

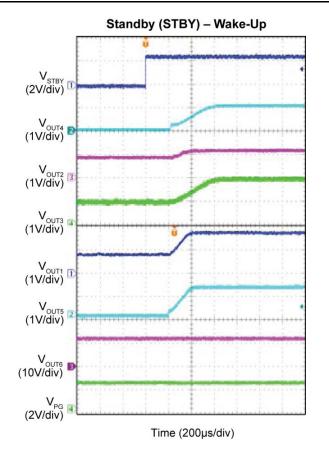
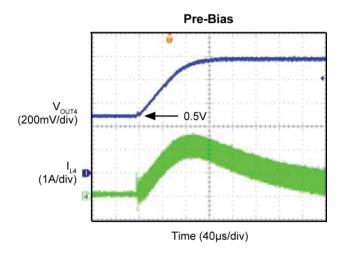


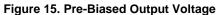
Figure 14. STBY-to-NORMAL Transition (DEFAULT)

#### Safe Start-Up into a Pre-Biased Output

The MIC7400 is designed for safe start-up into a prebiased output. This prevents large negative inductor currents which can cause the output voltage to dip and excessive output voltage oscillations. A zero crossing comparator is used to detect a negative inductor current. If a negative inductor current is detected, the low-side synchronous MOSFET functions as a diode and is immediately turned off.

Figure 15 shows a 1V output pre-bias at 0.5V at start-up, see  $V_{OUT4}$  trace. The inductor current, Trace  $I_{L4}$ , is not allowed to go negative by more than 0.5A before the low-side switch is turned off. This feature prevents high negative inductor current flow in a pre-bias condition which can damage the IC.





#### Buck Regulator Power Dissipation

The total power dissipation in a MIC7400 is a combination of the five buck regulators and the boost dissipation. The buck regulators (OUT1 to OUT5) dissipation is approximately the switcher's input power minus the switcher's output power and minus the power loss in the inductor:

$$P_{D_{BUCK}} \approx V_{IN} \times I_{IN} - V_{OUT} \times I_{OUT} - P_{L_{LOSS}}$$
 Eq. 4

While the boost power dissipation is estimated by Equation 5:

$$P_{D_{BOOST}} \approx V_{IN} \times I_{IN} - V_{OUT} \times I_{OUT} - P_{L_{LOSS}} - V_{f} \times I_{OUT}$$

Eq. 5

Although the maximum output current for a single buck regulator can be as much as 3A, the MIC7400 will thermal limit and will not support this high output current on all outputs at the same time.

#### **Total Power Dissipation**

The total power dissipation in the MIC7400 package is equal to the sum of the power loss of each regulator:

$$P_{D_{TOTAL}} \approx SUM (P_{D_{SWITCHERS}})$$
 Eq. 6

$$T_{J(MAX)} \approx T_A + P_{D_TOTAL} \times \theta_{JA}$$
 Eq. 7

Where:

 $T_{J(MAX)}$  = The maximum junction temperature

 $T_A$  = The ambient temperature

 $\theta_{JA}$  = The junction-to-ambient thermal resistance of the package (30°C/W)

Figure 16 shows the measured junction temperature versus power dissipation of the MIC7400 evaluation board. The actual junction temperature of the IC depends upon many factors. The significant factors influencing the die temperature rise are copper thickness in the PCB, the surface area available for convection heat transfer, air flow and power dissipation from other components, including inductors, SOCs and processor ICs. It is good engineering practice to measure all power components temperature during the final design review using a thermal couple or IR thermometer, see the "Thermal Measurements" sub-section for details.

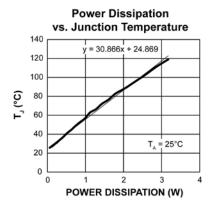


Figure 16. Power Dissipation

#### **Power Derating**

The MIC7400 package has a 2W power dissipation limit. To keep the IC junction temperature below a 125°C design limit, the output power has to be limited above an ambient temperature of 65°C. Figure 17 shows the power dissipation derating curve.

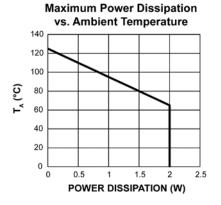


Figure 17. Power Derating Curve

The maximum power dissipation of the package can be calculated by Equation 8:

$$P_{D(MAX)} \approx \left( \frac{T_{J(MAX)} - T_A}{\theta_{JA}} \right)$$
 Eq. 8

Where:

 $T_{J(MAX)}$  = Maximum junction temperature (125°C)

 $T_A$  = Ambient temperature

 $\theta_{JA}$  = Junction-to-ambient thermal resistance of the package (30°C/W).

#### **Overtemperature Fault**

An overtemperature fault is triggered when the IC junction temperature reaches 160°C. When this occurs, both the overtemperature fault flag is set to "1", the global power good output is pulled low and all the outputs are turned off. During the fault condition the I<sup>2</sup>C interface remains active and all registers values are maintained.

When the die temperature decreases by 20°C the overtemperature fault bit can be cleared. To clear the fault, either recycle power or write a logic "0" to the over temperature fault register. Once the fault bit is cleared, the outputs power up to their default values and are sequenced according to the time slot settings.

#### Input Voltage "Hot Plug"

High-voltage spikes twice the input voltage can appear on the MIC7401 PVIN pins if a battery pack is hotplugged to the input supply voltage connection as shown in Figure 18 (Trace 1). These spikes are due to the inductance of the wires to the battery and the very low inductance and ESR of the ceramic input capacitors. This problem can be solved by placing a  $150\mu$ F POS capacitor across the input terminals. Figure 18 (Trace 2) shows that the high-voltage spike is greatly reduced to a value below the maximum allowable input voltage rating.

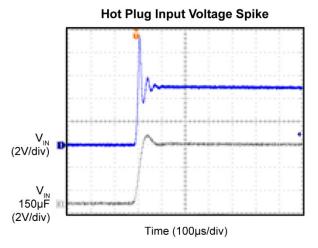


Figure 18. Hot Plug Input Voltage Spike

#### Thermal Measurements

Measuring the IC's case temperature is recommended to ensure it is within its operating limits. Although this might seem like a very elementary task, it is easy to get erroneous results. The most common mistake is to use the standard thermal couple that comes with a thermal meter. This thermal couple wire gauge is large (typically 22 gauge) and behaves like a heatsink, resulting in a lower case measurement.

Two reliable methods of temperature measurement are a smaller thermal couple wire or an infrared thermometer. If a thermal couple wire is used, it must be constructed of 36 gauge wire or higher (smaller wire size) to minimize the wire heat-sinking effect. In addition, the thermal couple tip must be covered in either thermal grease or thermal glue to make sure that the thermal couple junction is making good contact with the case of the IC. Omega brand thermal couple (5SC-TT-K-36-36) is adequate for most applications.

Whenever possible, an infrared thermometer is recommended. The measurement spot size of most infrared thermometers is too large for an accurate reading on a small form factor ICs. However, an IR thermometer from Optris has a 1mm spot size, which makes it a good choice for measuring the hottest point on the case. An optional stand makes it easy to hold the beam on the IC for long periods of time.

### **Timing Diagrams**

#### Normal Power-Up Sequence for Outputs

The STDEL register sets the delay between powering up of each regulator at initial power-up (see power-up sequencing in Figure 19). Once all the internal power good registers PGOOD[1-6] are all "1", then the global PG pin goes high without delay if the PGOOD\_MASK[6] bit is set to "0". The PORDEL register sets the delay for the POR flag pin. The POR delay time starts as soon as the AVIN pin voltage rises above the system UVLO upper threshold set by the PORUP register. The POR output goes low without delay if AVIN falls below the lower UVLO threshold set by the PORDN register.

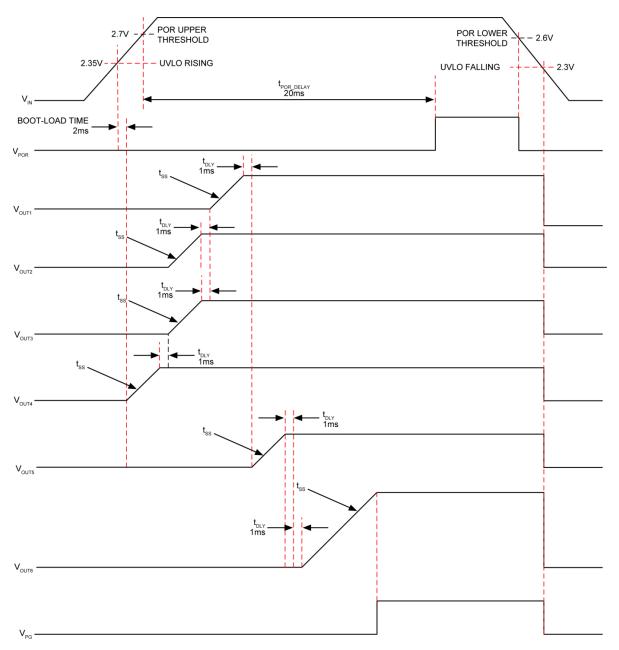
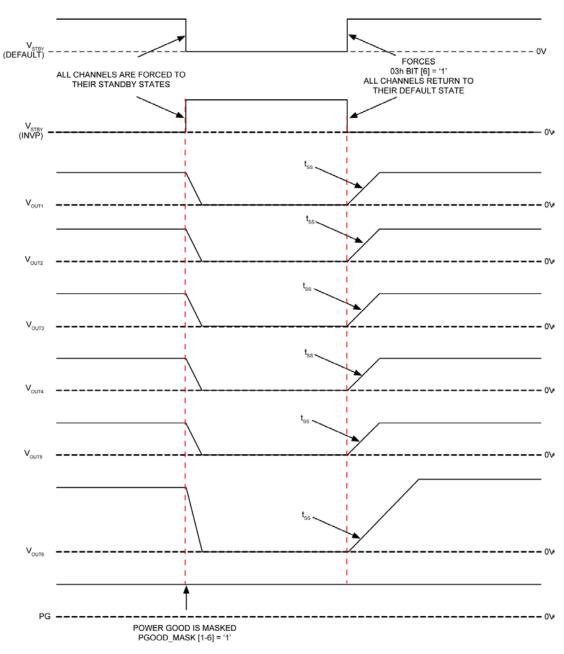


Figure 19. MIC7400 Power-Up/Down

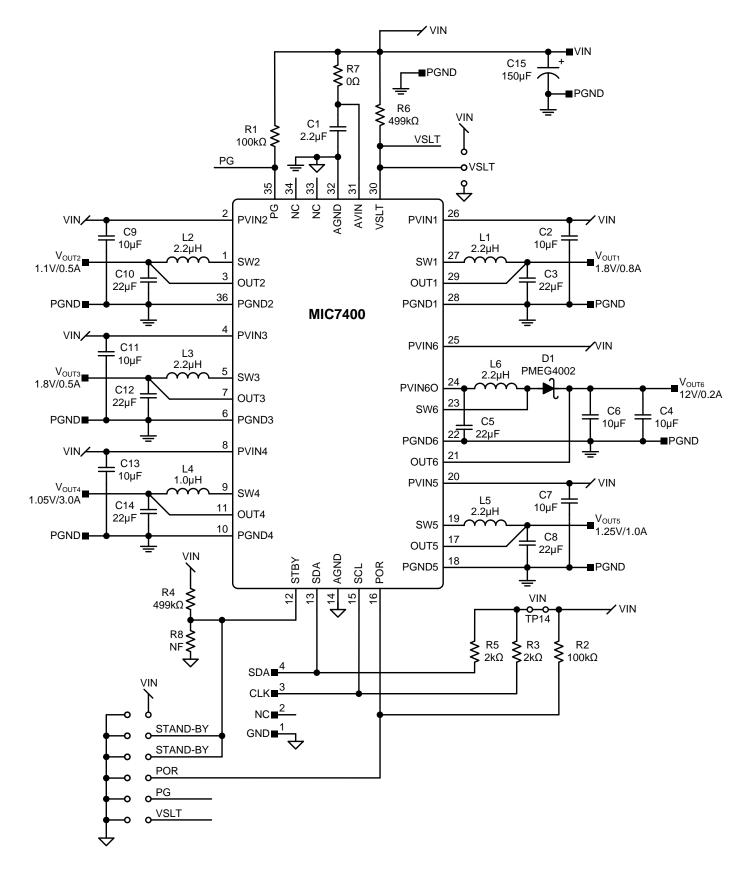
### Standby (STBY) Pin (Wake-Up)

An I<sup>2</sup>C write command to the STBY\_CTRL\_REG register or the STBY pin can be used to set the MIC7400 into stand-by mode. The standby (STBY) pin provides a hardware-specific manner in which to wake-up from stand-by mode and go into normal mode. Figure 20 shows the STBY pin operation. A low-to-high transition on the STBY pin switches the output from stand-by mode to normal mode. There is a 100µs STBY deglitch time to eliminate nuisance tripping, then all the regulators are enabled at the same time and ramp up with their programmed ramp rates.





## **Evaluation Board Schematic**



## **Bill of Materials**

ltem	Part Number	Manufacturer	Description	Qty.
C1	CL05A225KO5NQNC	Samsung <sup>(14)</sup>	2.2µF/16V, Ceramic, X5R, 0402, 0.8mm, ±10%	1
C2, C7, C9, C11, C13	CL10A106MO8NQNC	L10A106MO8NQNC Samsung 10µF/16V, Ceramic, X5R, 0603, 0.8mm, ±20%		5
C4, C6	CL21A106KAYNNNE	Samsung	10μF/25V, Ceramic, X5R, 0805, 1.25mm, ±20%	2
C3, C5, C8, C10, C12, C14	CL10A226MQ8NUNE	Samsung	22µF/6.3V, Ceramic, X5R, 0603, 0.8mm, ±20%	
C15	EEF-CX0J151XR	Panasonic	150µF/6.3V, POS Capacitor, SP, ±20%	1
D1	PMEG4002EL	NXP <sup>(15)</sup>	0.2A/40V, Schottky, SOD-882	1
R1, R2	RC1005F104CS	Samsung	100kΩ, Resistor, 0402, 1%	3
R3, R5	RC1005F202CS	Samsung	2.0kΩ, Resistor, 0402, 1%	2
R4, R6	RC1005F4993CS	Samsung	499kΩ, Resistor, 0402, 1%	1
R7	RC1005J000CS	Samsung	0.00Ω, Resistor, 0402, Jumper	1
L1, L2, L3, L5, L6	CIG22H2R2MNE	Samsung	2.2µH, 1.6A Inductor, 116mΩ, 2520 × 1.2mm (max)	5
L4	CIGW252010GM1R0MNE	Samsung	1.0µH, 3.3A Inductor 40mΩ, 2520 × 1.0mm (max)	1
U1	MIC7400YFL	Micrel <sup>(16)</sup>	Five-Channel Buck Regulator Plus One Boost with HyperLight Load <sup>®</sup> and I <sup>2</sup> C Control	

Notes:

14. Samsung: www.samsung.com.

15. NXP: <u>www.nxp.com</u>.

16. Micrel, Inc.: <u>www.micrel.com</u>.

## **PCB Layout Guidelines**

# Warning!!! To minimize EMI and output noise, follow these layout recommendations.

PCB layout is critical to achieve reliable, stable, and efficient performance. A ground plane is required to control EMI and minimize the inductance in power, signal, and return paths.

The following guidelines should be followed to ensure proper operation:

#### General

- Most of the heat removed from the IC is due to the exposed pad (EP) on the bottom of the IC conducting heat into the internal ground planes and the ground plane on the bottom side of the board. Use at least 16 vias for the EP to ground plane connection.
- Do not connect the PGND and AGND traces together on the top layer. The single point connection is made on the layer 2 ground plane.
- Do not put a via directly in front of a high current pin, SW, PGND, or PVIN. This will increase the trace resistance and parasitic inductance.
- Do not place a via in between the input and output capacitor ground connection. Put it to the inside of the output capacitor and in the way of the high di/dt current path.
- Route all power traces on the top layer, as shown in the example layout.
- Place the input capacitors first and put them as close as possible to the IC.

## IC

- The 2.2µF ceramic capacitor, which is connected to the AVIN pin, must be located right at the IC. The AVIN pin is very noise sensitive and placement of the capacitor is very critical. Use wide traces to connect to the AVIN and AGND pins.
- The analog ground pin (AGND) must be connected directly to the ground planes. Do not route the SGND pin to the PGND Pad on the top layer.
- Use fat traces to route the input and output power lines.
- Use Layer 5 as an input voltage power plane.
- Layer 2 and the bottom layer (Layer 6) are ground planes.

#### Input Capacitor

- A 10µF X5R or X7R dielectrics ceramic capacitor is recommended on each of the PVIN pins for bypassing.
- Place the input capacitors on the same side of the board and as close to the IC as possible.
- Keep both the PVIN pin and PGND connections short.
- If possible, place vias to the ground plane close to the each input capacitor ground terminal, but not in the way of the high di/dit current path.
- Use either X7R or X5R dielectric input capacitors. Do not use Y5V or Z5U type capacitors.
- Do not replace the ceramic input capacitor with any other type of capacitor. Any type of capacitor can be placed in parallel with the input capacitor.
- In "Hot-Plug" applications, a Tantalum or Electrolytic bypass capacitor must be used to limit the over-voltage spike seen on the input supply with power is suddenly applied.

#### Inductor

- Keep the inductor connection to the switch node (SW) short.
- Do not route any digital lines underneath or close to the inductor.
- To minimize noise, place a ground plane underneath the inductor.

#### **Output Capacitor**

- Use a wide trace to connect the output capacitor ground terminal to the input capacitor ground terminal. In the example layout, all input and output capacitor ground connections are place back-to-back.
- The OUT[1-6] trace should be separate from the power trace and connected as close as possible to the output capacitor. Sensing a long high-current load trace can degrade the DC load regulation.

## **Proper Termination of Unused Pins**

Many designs will not require all six DC-to-DC output voltages. In these cases, the unused pin must be connected to either  $V_{\rm IN}$  or GND.

The schematic in Figure 21 shows where to tie the unused pins and Table 4 summarizes the connections.

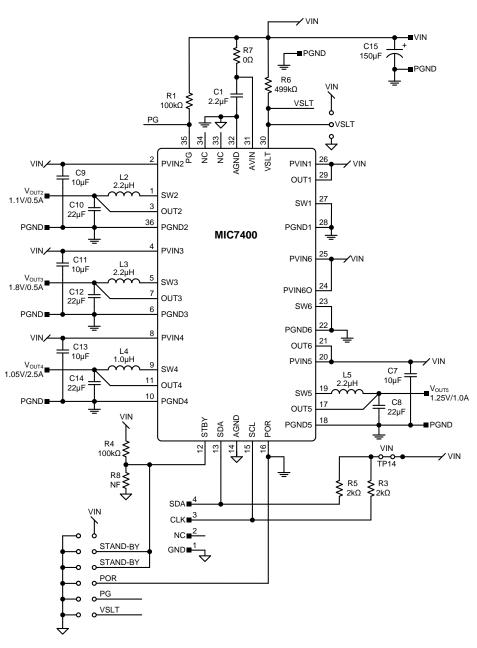
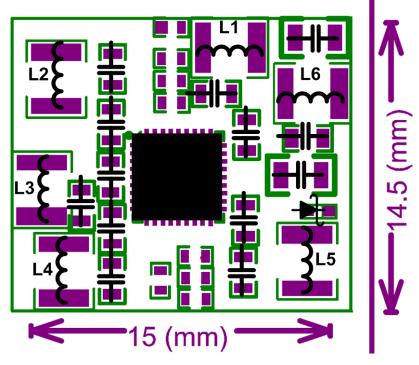


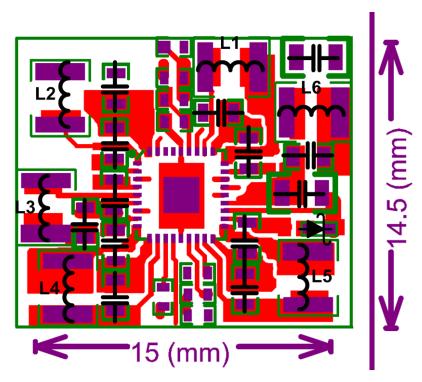
Figure 21. Connections for Unused Pins

Unused	VIN	PGND
Boost	PVIN6, PGIN6O, VOUT6	PGND6, SW6
Buck	PVIN[x], VOUT[x}	PGND[6], SW[x]
POR		POR

## PCB Layout Recommendations

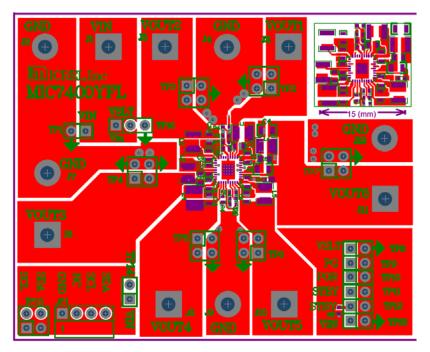


Evaluation Board Top Layer – Power Component Placement

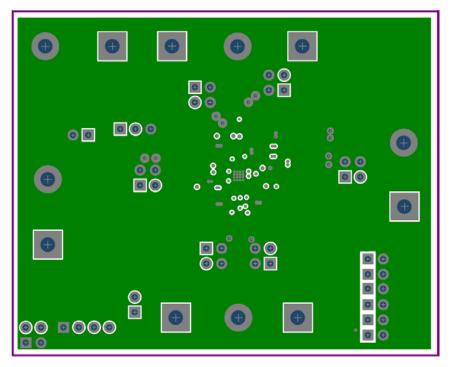


Evaluation Board Top Layer – Layer 1 (Power Routing Layer)

## PCB Layout Recommendations (Continued)

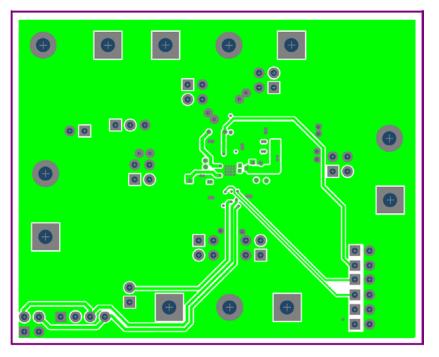


Evaluation Board Top Layer – Layer 1 (Power Routing Layer)

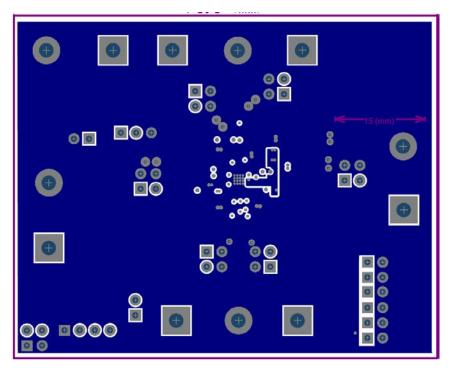


Evaluation Board Layer 2 (Ground Plane)

## PCB Layout Recommendations (Continued)

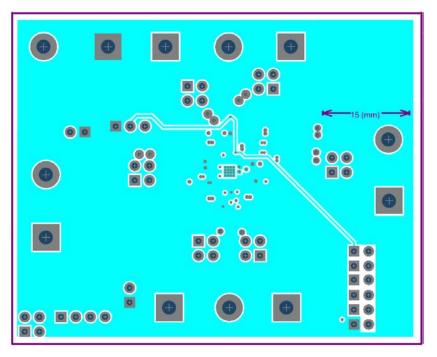


Evaluation Board Top Layer – Layer 3 (Signal Routing Layer)

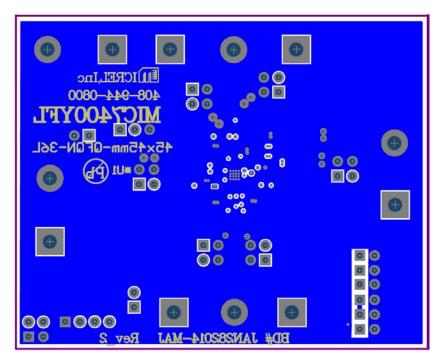


**Evaluation Board Layer 4 (Ground Plane)** 

## PCB Layout Recommendations (Continued)

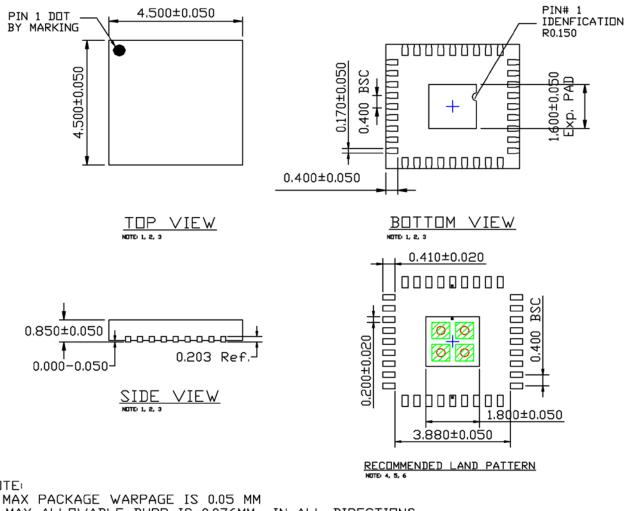


Evaluation Board Layer – Layer 5 (V<sub>IN</sub> Plane)



Evaluation Board Bottom Later – Layer 6 (Ground Plane)





NDTE:

1. MAX PACKAGE WARPAGE IS 0.05 MM

2. MAX ALLOWABLE BURR IS 0.076MM IN ALL DIRECTIONS

3. PIN #1 IS ON TOP WILL BE LASER MARKED

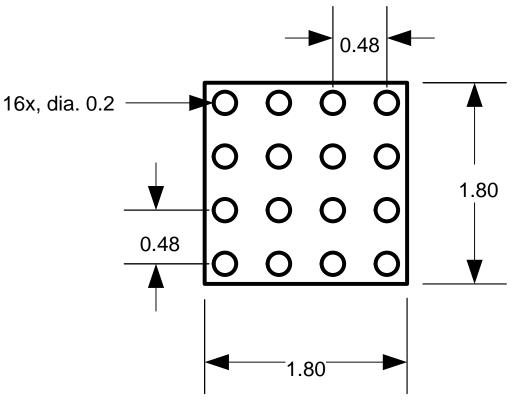
4. RED CIRCLE IN LAND PATTERN REPRESENT THERMAL VIA. SIZE SHOULD BE 0.30-0.35MM IN DIAMETER, 0.8MM PITCH & MUST BE CONNECTED TO GND FOR MAX THERMAL PERFORMANCE 5. GREEN RECTANGLES (SHADED AREA, OPTIONAL) REPRESENT SOLDER STENCIL OPENING ON EXPOSED PAD AREA. SIZE SHOULD BE 0.60X0.60 MM IN SIZE, 0.20MM SPACING. 6. LAND PATTERN OPENINGS MARKED BY "\*" (PINS#14, 32 & EPAD) ARE OF SAME GND AND SHOULD BE CONNECTED ON BOARD LEVEL FOR MAXIMUM THERMAL PERFORMANCE

#### 36-Pin 4.5mm × 4.5mm FQFN (FL)

#### Note:

17. Package information is correct as of the publication date. For updates and most current information, go to www.micrel.com.

## Via Layout Design and Layout Constraints



Via Layout Design

#### Notes:

Dimensions in millimeters (mm).

This package is designed to be soldered to a thermal pad on the board. Connect all ground planes together

Customers should contact their board fabrication site for recommended solder mask tolerance and via tenting recommendations for vias placed in the thermal pad.

## I<sup>2</sup>C Control Register

The MIC7400 I<sup>2</sup>C Read/Write registers are detailed here. During normal operation, the configuration data can be saved into non-volatile registers in EEPROM by addressing the chip and writing to SAVECONFIG key = 66'h. Saving CONFIG data to EEPROM takes time so the external host should poll the MIC7400 and read the CONFIG bit[1] of EEPROM Ready register 01'h to determine the end of programming.

All transactions start with a control byte sent from the I<sup>2</sup>C master device. The control byte begins with a START condition, followed by a 7-bit slave address. The slave address is seven bits long followed by an eighth bit which is a data direction bit (R/W), a "0" indicates a transmission (WRITE) and a "1" indicates a request for data (READ). A data transfer is always terminated by a STOP condition that is generated by the master.

## **Serial Port Operation**

## External Host Interface

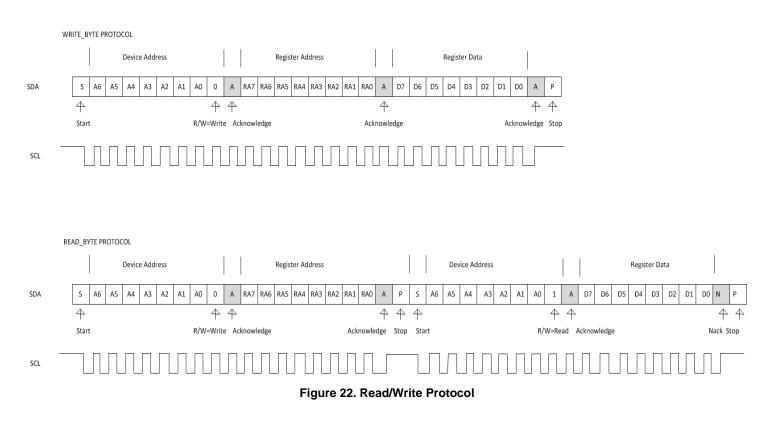
Bidirectional I<sup>2</sup>C port capable of Standard (up to 100kbits/s), Fast (up to 400kbits/s), Fast Plus (up to 1Mbit/s) and High Speed (up to 3.4Mbit/s) as defined in the I<sup>2</sup>C-Bus Specification.

The MIC7400 acts as an I<sup>2</sup>C slave when addressed by the external host. The MIC7400 slave address uses a fixed 7-bit code and is followed by an R/W bit which is part of the control word that is right after the start bit as shown in Figure 22 in the Device Address column.

The MIC7400 can receive multiple data bytes after a single address byte and automatically increments its register pointer to block fill internal volatile memory. Byte data is latched after individual bytes are received so multi-byte transfers could be corrupted if interrupted mid-stream.

No system clock is required by the digital core for I<sup>2</sup>C access from the external host (only the host SCL clock is assumed).

In order to prevent spurious operation of the  $I^2C$ , if a start bit is seen, then any partial communication is aborted and new  $I^2C$  data is allowed. Start bit is when SDA goes low when SCL is high. Stop bit is when SDA goes high when SCL is high. Normal  $I^2C$  exchange is shown in Figure 22.



## Special Host I<sup>2</sup>C Commands

The following commands are all 2 byte communications:

Byte1 = device address with write bit set, LSB = 0

Byte2 = special key

## Special Keys

- SAVECONFIG Key = 66'h. Saves the shadow register configuration data into EEPROM registers 03'h thru 23'h.
- **RESET Key = 6A'h**. Reloads only NORMAL mode voltage and current limit settings then enables the regulator to NORMAL mode with no soft-start, no sequencing, and no delays. Then clears the STANDBY register bit 6 in register 03'h.
- **RELOAD Key = 6B'h**. Reloads all data from EEPROM into the shadow registers. No other actions are performed, including soft-start, sequencing, and delay.
- **REBOOT Key = 6C'h**. Turns all regulators OFF, reloads EEPROM data into shadow registers, then re-sequences the regulators with the programmed soft-start and sequence delays.
- SEQUENCE Key = 6D'h. Turns all regulators OFF, restarts the sequencer including soft-start and sequence delays.

## Appendix B

## **Register Settings Descriptions**

## Power Good Register (00'h)

This register indicates when the regulators 1 - 6 output voltage is above 91% of the target value. The MIC7400 deglitches the input signal for 50µs in order to prevent false events. The global PG pin indicator is functional 'AND' of all the power good indicators during sequencing. Once the power-up sequence is complete, the global power good output stays high unless an output falls below its power-good limit, a thermal fault occurs, the input voltage drops below the lower UVLO threshold or an output is turned OFF by setting the enable register bit to "0" if the PGOOD\_MASK[x] bit is set to "0".

#### Table 5. Power Good Status Register

Register Name	PGOOD1-6_REG			Power Good Status	s Register			
Address		PGOOD	1-6_REG	0x00'h				
Field	bit	R/W	Default	Descriptio	n			
DC00D4	_	R	0	Power Good indicator for	or Regulator 1			
PGOOD1	0	ĸ	0	0 = Buck Not Valid	1 = Buck Valid			
B000D2	4	D	0	Power Good indicator f	or Regulator 2			
PGOOD2	1	R	0	0 = Buck Not Valid	1 = Buck Valid			
<b>DCOOD</b> 2				2 R 0		Power Good indicator f	or regulator 3	
PGOOD3	2	2 K	0	0 = Buck Not Valid	1 = Buck Valid			
D000D4	0	6	0	Power Good indicator f	or Regulator 4			
PGOOD4	3	R	R 0	0 = Buck Not Valid	1 = Buck Valid			
DOODE		D	0	Power Good indicator f	or Regulator 5			
PGOOD5	4	R		R	0	0 = Buck Not Valid	1 = Buck Valid	
500050	_	6		Power Good indicator fo	or Regulator 6			
PGOOD6	5	R	0	0 = Boost Not Valid	1 = Boost Valid			
Reserved	6	R/W	0	Not Used				
Reserved	7	R/W	0	Not Used				

## EEPROM-Ready Register (01'h)

This register indicates the status of EEPROM to external I<sup>2</sup>C host.

The READY bit = 1 when the Trim and Configuration data have been loaded into core from EEPROM after reset, reboot or reload and the chip is ready for operation. [If the SAVE1 bit in register 04'h is read in as logic 1, the configuration registers will not be loaded from the EEPROM memory and the READY bit will still get set indicating that any startup procedure involving the EEPROM memory is complete.] The READY bit will be set to 1 after loading or attempting to load Trim and Configuration data from EEPROM into volatile memory. The Trim data will always be loaded and if SAVE1 bit in register 04'h is set to logic 0, Configuration data is also loaded. Regardless of the SAVE1 bit being set or not, after the loading operation the READY bit is set to 1.

The CONFIG bit = 1 when the Configuration data have been saved to EEPROM after the SAVECONFIG Code is issued from the Host. If CONFIG=1 before the SAVECONFIG code is issued, CONFIG will be cleared immediately and then will be set to logic 1 again once all Configuration data is written to the EEPROM memory.

The CALIB bit = 1 when the Trim data have been saved to EEPROM after the SAVETRIM Code is issued from the Host. If CALIB=1 before the SAVETRIM code is issued, CALIB will be cleared immediately and then will be set to logic 1 again once all Trim data is written to the EEPROM memory.

The EEPREAD and EEPWRITE bits indicate if an EEPROM read or write fault has occurred. These bits should be read and cleared prior to reloading data from the EEPROM memory.

Register Name	S	TATUS_	REG	EEPROM Status Register		
Address				0x01'h		
Field	bit	R/W	Default	Description		
	•	<b>_</b>		Indicate ready for operation when the tr	im and configuration data has been loaded	
READY	0	R	0	0 = Data not loaded	1 = Chip Ready	
				Indicate Configuration saved to EEPRC	DM	
CONFIG	1	R	0	0 = Configuration not saved	1 = Configuration Saved	
0.41.15			_	Indicate trim data have been saved to EEROM		
CALIB	2	2 R	0	0 = Trim not saved	1 = Trim saved	
Reserved	3	R/W	0	Not Used		
Reserved	4	R/W	0	Not Used		
Reserved	5	R/W	0	Not Used		
	0		_	EEPROM Read		
EEPREAD	6	6 R/W 0		0 = No Fault	1 = Fault	
	7		_	EEPROM Write	·	
EEPWRITE	7	R/W	0	0 = No Fault	1 = Fault	

#### Table 6. EEPROM Status Register

## Fault Registers (02'h)

This register indicates the over-current flag for each regulator and one global overtemperature (OT). These register bits are set by an over current condition and reset by writing a logic "0" to each bit by the I<sup>2</sup>C host.

If the fault condition persists, the bit will be set to logic "1" again immediately by the MIC7400 after it is written to logic "0" by the host.

Register Name	FAULT_REG		REG	Overcurrent Status Fault Register			
Address				0x02'h			
Field	bit	R/W	Default	Description			
DE0100	0		0	Regulator 1 Overcurrent			
REG1OC	0	R/W	0	0 = No Fault	1 = Fault		
REG2OC	1	R/W	0	Regulator 2 Overcurrent			
REG2OC	I	R/W	0	0 = No Fault	1 = Fault		
REG3OC	2	DAM 0		DAN		Regulator 3 Overcurrent	
REG3OC	2 F	R/W	0	0 = No Fault	1 = Fault		
REG4OC	100		0	Regulator 4 Overcurrent			
REG40C	3	R/W	0	0 = No Fault	1 = Fault		
REG5OC	4	R/W	0	Regulator 5 Overcurrent			
REGSOC	4		0	0 = No Fault	1 = Fault		
REG6OC	5	R/W	0	Regulator 6 Overcurrent			
REGOOC	5	R/W	0	0 = No Fault	1 = Fault		
Reserved	6	R/W	0	Reserved			
от	7	R/W		Overtemperature			
	1	FX/ VV	0	0 = No Fault	1 = Fault		

Table 7. Overcurrent Status Fault Register

### Standby Register (03'h)

This register controls standby mode operation. Global stand-by mode can either be enabled by  $I^2C$  or by changing the logic state of the STBY input pin. Global stand-by is controlled by the STBY\_MODEB bit. When STBY\_MODEB [6] = 1 then the regulators output voltages are set to their normal-mode output voltage settings, (05'h - 0A'h) registers. When STBY\_MODEB [6] = 0 then regulators output voltages are set to the standby-mode output voltage settings, (0B'h - 10'h) registers. If STBY [1-6] register is set to logic "0", then the output is shut off in standby mode.

The global power good flag is asserted when an output is disabled unless the power good mask bit (PGOOD\_MASK[x]) is set to 1.

Register Name	ST	BY_CTI	RL_REG	Standby Register		
Address				0x03'h		
Field	bit	R/W	Default	Description		
	0		4	Regulator 1 Standby Voltage Control		
STBY1	0	R/W	1	0 = OFF	1 = ON	
OTDV2			4	Regulator 2 Standby Voltage Control		
STBY2	1	R/W	1	0 = OFF	1 = ON	
OTDV2	0			Regulator 3 Standby Voltage Control		
STBY3	2	R/W	1	0 = OFF	1 = ON	
STDV4	2	R/W	1	Regulator 4 Standby Voltage Control		
STBY4	3			0 = OFF	1 = ON	
STRVE	4	R/W	1	Regulator 5 Standby Voltage Control		
STBY5	4	K/W	I	0 = OFF	1 = ON	
STBY6	5	R/W	1	Regulator 6 Standby Voltage Control		
51610	5	K/VV	1	0 = OFF	1 = ON	
				Global Standby Control		
STBY_MODEB	ODEB 6 R/W		1	0 = All regulators in Standby Mode		
				1 = All regulators in Normal Mode		
Reserved	7	R/W	0	Not Used		

#### Table 8. Standby Register

## Enable/Disable Register (04'h)

This register controls the enable/disable of each DC-to-DC regulators. When EN(n) bit transitions from "0" to "1", then the regulator(n) is enabled with soft-start unless the STBY\_MODEB register bit in register 03'h is set to logic "0".

The configuration save bit "SAVE1" should be cleared by customer before saving configuration data to EEPROM. This bit is used during power up to indicate via the Status register (00'h) that configuration data has previously been stored.

Register Name		EN_RI	EG	Enable Register				
Address				0x04'h				
Field	bit	R/W	Default	Description				
			4	Regulator 1 ON/OFF Control bit	t			
EN1	0	R/W	1	0 = OFF	1 = ON			
				Regulator 2 ON/OFF Control bit	t			
EN2	1	R/W	1	0 = OFF	1 = ON			
	0			Regulator 3 ON/OFF Control				
EN3	2	2 R/W	1	0 = OFF	1 = ON			
				Regulator 4 ON/OFF Control				
EN4	3	R/W	1	0 = OFF	1 = ON			
	4		4	Regulator 5 ON/OFF Control				
EN5	4	R/W	1	0 = OFF	1 = ON			
	-		4	Regulator 6 ON/OFF Control				
EN6	5	R/W	1	0 = OFF	1 = ON			
Reserved	6	R/W	0	Not Used				
				Save Configuration				
SAVE1	7	R/W	0	0 = Configuration Saved to EEPROM				
				1 = Not Configuration Saved to	EEPROM			

#### Table 9. Enable Register

## Regulator Output Voltage Setting NORMAL Mode (05'h - 09'h)

One register for each regulator output (OUT1 – OUT5). Sets output voltage of regulator for NORMAL mode operation.

## Table 10. DVC Registers for OUT[1 - 5]

Register Name		OUT1-5_REG DVC Registers for OUT[1-5]						
				OUT1 = 0x05'h OUT2 = 0x06'h				
Address				OUT3 = 0x07'h				
				OUT4 = 0x08'h				
				OUT5 = 0x09'h				
Field	bit	R/W	Default	Description				
				Output Voltage sett DVC from 3.3 V to	ting of OUT[1-5] 0.8V in -50mV steps			
				000000 = 3.30V	010000 = 2.50V	100000 = 1.70V	110000 = 0.90V	
				000001 = 3.25V	010001 = 2.45V	100001 = 1.65V	110001 = 0.85V	
				000010 = 3.20V	010010 = 2.40V	100010 = 1.60V	110010 = 0.80V	
				000011 = 3.15V	010011 = 2.35V	100011 = 1.55V	110011 = 0.80V	
				000100 = 3.10V	010100 = 2.30V	100100 = 1.50V	110100 = 0.80V	
				000101 = 3.05V	010101 = 2.25V	100101 = 1.45V	110101 = 0.80V	
				000110 = 3.00V	010110 = 2.20V	100110 = 1.40V	110110 = 0.80V	
OUT[1-5]	5:0	R/W	See Table 2	000111 = 2.95V	010111 = 2.15V	100111 = 1.35V	110111 = 0.80V	
				001000 = 2.90V	011000 = 2.10V	101000 = 1.30V	111000 = 0.80V	
				001001 = 2.85V	011001 = 2.05V	101001 = 1.25V	111001 = 0.80V	
				001010 = 2.80V	011010 = 2.00V	101010 = 1.20V	111010 = 0.80V	
				001011 = 2.75V	011011 = 1.95V	101011 = 1.15V	111011 = 0.80V	
				001100 = 2.70V	011100 = 1.90V	101100 = 1.10V	111100 = 0.80V	
				001101 = 2.65V	011101 = 1.85V	101101 = 1.05V	111101 = 0.80V	
				001110 = 2.60V	011110 = 1.80V	101110 = 1.00V	111110 = 0.80V	
				001111 = 2.55V	011111 = 1.75V	101111 = 0.95V	111111 = 0.80V	
	6		0	Not Used				
	7		0	Not Used				

## Boost Regulator Output Voltage Setting NORMAL Mode (0A'h)

Sets output voltage of the boost regulator (OUT6) in NORMAL mode operation.

### Table 11. DVC Registers for OUT6

Register Name	OUT6_REG DVC Registers						
Address				0x0A'h			
Field	bit	R/W	Default	Description			
				DVC from 14V to 7	V in 200mV decrement	S	
				000000 = 14.0V	010000 = 10.8V	100000 = 7.6V	110000 = 7.0V
				000001 = 13.8V	010001 = 10.6V	100001 = 7.4V	110001 = 7.0V
				000010 = 13.6V	010010 = 10.4V	100010 = 7.2V	110010 = 7.0V
				000011 = 13.4V	010011 = 10.2V	100011 = 7.0V	110011 = 7.0V
				000100 = 13.2V	010100 = 10.0V	100100 = 7.0V	110100 = 7.0V
				000101 = 13.0V	010101 = 9.8V	100101 = 7.0V	110101 = 7.0V
				000110 = 12.8V	010110 = 9.6V	100110 = 7.0V	110110 = 7.0V
OUT6	5:0	R/W	See Table 2	000111 = 12.6V	010111 = 9.4V	100111 = 7.0V	110111 = 7.0V
				001000 = 12.4V	011000 = 9.2V	101000 = 7.0V	111000 = 7.0V
				001001 = 12.2V	011001 = 9.0V	101001 = 7.0V	111001 = 7.0V
				001010 = 12.0V	011010 = 8.8V	101010 = 7.0V	111010 = 7.0V
				001011 = 11.8V	011011 = 8.6V	101011 = 7.0V	111011 = 7.0V
				001100 = 11.6V	011100 = 8.4V	101100 = 7.0V	111100 = 7.0V
				001101 = 11.4V	011101 = 8.2V	101101 = 7.0V	111101 = 7.0V
				001110 = 11.2V	011110 = 8.0V	101110 = 7.0V	111110 = 7.0V
				001111 = 11.0V	011111 = 7.8V	101111 = 7.0V	111111 = 7.0V
	6		0	Not Used			
	7		0	Not Used			

## Regulator Voltage Setting STBY Mode (0B'h – 0F'h)

This register is used to sets the output voltage of regulators 1 - 5 in STBY mode operation.

#### Table 12. Standby Registers

Register Name	ST	BY_OU	OUT1-5_REG Standby DVC Registers					
Address				OUT1 = 0x0B'h $OUT2 = 0x0C'h$ $OUT3 = 0x0D'h$ $OUT4 = 0x0E'h$ $OUT5 = 0x0F'h$				
Field	bit	R/W	Default	Description				
SB_OUT[1-5]	5:0	R/W	See Table 2	Output Voltage set DVC from 3.3 V to 000000 = 3.30V 00001 = 3.25V 000010 = 3.20V 00010 = 3.10V 000101 = 3.00V 000110 = 3.00V 000111 = 2.95V 001000 = 2.90V 001001 = 2.80V 001011 = 2.85V 001011 = 2.75V 001100 = 2.70V	ting of OUT[1-5]         0.8V in -50mV steps         010000 = 2.50V         010001 = 2.45V         010010 = 2.40V         010011 = 2.35V         010100 = 2.30V         010101 = 2.25V         010110 = 2.20V         010111 = 2.25V         010110 = 2.20V         010110 = 2.20V         011000 = 2.10V         011001 = 2.05V         011001 = 2.00V         011011 = 1.95V         011100 = 1.90V         011101 = 1.85V	100000 = 1.70V 100001 = 1.65V 100010 = 1.60V 100010 = 1.50V 100100 = 1.50V 100101 = 1.45V 100110 = 1.40V 100111 = 1.35V 101000 = 1.30V 101001 = 1.20V 101011 = 1.15V 101100 = 1.10V 101101 = 1.05V	110000 = 0.90V 110001 = 0.85V 110010 = 0.80V 110011 = 0.80V 110100 = 0.80V 110101 = 0.80V 110110 = 0.80V 110111 = 0.80V 111001 = 0.80V 111011 = 0.80V 111011 = 0.80V 111101 = 0.80V	
				001110 = 2.60V 001111 = 2.55V	011110 = 1.80V 011111 = 1.75V	101110 = 1.00V 101111 = 0.95V	111110 = 0.80V 111111 = 0.80V	
	6		0	Not Used	•		-	
	7		0	Not Used				

## Boost Regulator Output Voltage Setting STBY Mode (10'h)

Sets output voltage of the boost regulator (OUT6) for STBY mode operation.

### Table 13. Standby DVC Register for OUT6

Register Name	S	TBY _OI	JT6_REG	DVC Registers					
Address				0x10'h					
Field	bit	R/W	Default	Description					
				DVC from 14V to 7	V in 200mV decrement	s			
				000000 = 14.0V	010000 = 10.8V	100000 = 7.6V	110000 = 7.0V		
				000001 = 13.8V	010001 = 10.6V	100001 = 7.4V	110001 = 7.0V		
				000010 = 13.6V	010010 = 10.4V	100010 = 7.2V	110010 = 7.0V		
				000011 = 13.4V	010011 = 10.2V	100011 = 7.0V	110011 = 7.0V		
				000100 = 13.2V	010100 = 10.0V	100100 = 7.0V	110100 = 7.0V		
				000101 = 13.0V	010101 = 9.8V	100101 = 7.0V	110101 = 7.0V		
				000110 = 12.8V	010110 = 9.6V	100110 = 7.0V	110110 = 7.0V		
SB_OUT6	5:0	R/W	See Table 2	000111 = 12.6V	010111 = 9.4V	100111 = 7.0V	110111 = 7.0V		
				001000 = 12.4V	011000 = 9.2V	101000 = 7.0V	111000 = 7.0V		
				001001 = 12.2V	011001 = 9.0V	101001 = 7.0V	111001 = 7.0V		
				001010 = 12.0V	011010 = 8.8V	101010 = 7.0V	111010 = 7.0V		
				001011 = 11.8V	011011 = 8.6V	101011 = 7.0V	111011 = 7.0V		
				001100 = 11.6V	011100 = 8.4V	101100 = 7.0V	111100 = 7.0V		
				001101 = 11.4V	011101 = 8.2V	101101 = 7.0V	111101 = 7.0V		
				001110 = 11.2V	011110 = 8.0V	101110 = 7.0V	111110 = 7.0V		
				001111 = 11.0V	011111 = 7.8V	101111 = 7.0V	111111 = 7.0V		
	6		0	Not Used					
	7		0	Not Used					

## Sequence Register (11'h)

Each regulator can be assigned to start in any one of six sequencing slots (1 to 6). If starting in slot 1, the regulator starts immediately. If starting in any other slot the regulator must wait for the PGOOD=1 flags of all regulators assigned to the preceding slot and then wait for the specified delay time (register 17'h) i.e., all PGOODs in preceding state flag then the delay timer is started and when delay completes the regulator is enabled.

Each regulator must delay its startup (after the appropriate preceding PGOOD flags) by the delay set in the Delay Register (17'h), unless the regulator is assigned to sequence state 0.

If all default Enable bits = 0 the IC starts up, but no outputs are enabled.

Sequencing is only used during initial startup, and not used when outputs are enabled via I<sup>2</sup>C command. If outputs are enabled via I<sup>2</sup>C then soft-start is still active but start-up delays (timed from preceding PGOODs) are not.

Register Name		SEQ1_F	REG	Sequence Register				
Address				0x11'h				
Field	bit	R/W	Default	Description				
REG1SQ1	0	R/W	0					
REGISQI	0		0	0 = No Start	1 = Regulator 1 will Start in Sequence State 1			
REG2SQ1	1	R/W	0					
REGZOGI	'	17/11	0	0 = No Start	1 = Regulator 2 will Start in Sequence State 1			
REG3SQ1	2	R/W	0					
RECOOL	2	10,00	0	0 = No Start	1 = Regulator 3 will Start in Sequence State 1			
REG4SQ1	3	R/W	1					
NEO-OQT	Ŭ	10,00		0 = No Start	1 = Regulator 4 will Start in Sequence State 1			
REG5SQ1	4	R/W	0					
HECCOQ.		1011	Ű	0 = No Start	1 = Regulator 5 will Start in Sequence State 1			
REG6SQ1	5	R/W	0					
HEODOG I	Ŭ	1011	Ű	0 = No Start	1 = Regulator 6 will Start in Sequence State 1			
	6	R/W	0	Reserved				
	7	R/W	0	Reserved				

Table 14. Sequence State 1 Register

#### Table 15. Sequence State 2 Register

Register Name		SEQ2_F	REG	Sequence Register				
Address				0x12'h				
Field	bit	R/W	Default	Description				
DE01000			0					
REG1SQ2	0	R/W	0	0 = No Start	1 = Regulator 1 will Start in Sequence State 2			
DEC2802	4	R/W	1					
REG2SQ2	1	r./ v v	1	0 = No Start	1 = Regulator 2 will Start in Sequence State 2			
DEC2802	2		1					
REG3SQ2	2	R/W	1	0 = No Start	1 = Regulator 3 will Start in Sequence State 2			
REG4SQ2	3	R/W	0					
REG43Q2	5		U	0 = No Start	1 = Regulator 4 will Start in Sequence State 2			
REG5SQ2	4	R/W	0					
REG33Q2	4		U	0 = No Start	1 = Regulator 5 will Start in Sequence State 2			
REG6SQ2	5	R/W	0					
REGOSQZ	5		0	0 = No Start	1 = Regulator 6 will Start in Sequence State 2			
	6	R/W	0	Reserved				
	7	R/W	0	Reserved				

### Table 16. Sequence State 3 Register

Register Name		SEQ3_F	REG	Sequence Register				
Address				0x13'h				
Field	bit	R/W	Default	Description				
BEC1802	0		4					
REG1SQ3	0	R/W	1	0 = No Start	1 = Regulator 1 will Start in Sequence State 3			
REG2SQ3	1	R/W	0					
REG23Q3	I	r/w	0	0 = No Start	1 = Regulator 2 will Start in Sequence State 3			
REG3SQ3	2	R/W	0					
REG33Q3	Z	r/w	0	0 = No Start	1 = Regulator 3 will Start in Sequence State 3			
REG4SQ3	3	R/W	0					
REG43Q3	3	R/W	0	0 = No Start	1 = Regulator 4 will Start in Sequence State 3			
REG5SQ3	4	R/W	0					
REG33Q3	4		0	0 = No Start	1 = Regulator 5 will Start in Sequence State 3			
REG6SQ3	5	R/W	0					
REG03Q3	5		0	0 = No Start	1 = Regulator 6 will Start in Sequence State 3			
	6	R/W	0	Reserved				
	7	R/W	0	Reserved				

#### Table 17. Sequence State 4 Register

Register Name		SEQ4_F	REG	Sequence Register				
Address				0x14'h				
Field	bit	R/W	Default	Description				
REG1SQ4	0	R/W	0					
REGI3Q4	0	r///	0	0 = No Start	1 = Regulator 1 will Start in Sequence State 4			
REG2SQ4	1	R/W	0					
RE02304	1		0	0 = No Start	1 = Regulator 2 will Start in Sequence State 4			
REG3SQ4	2	R/W	0					
RE03304	2		0	0 = No Start	1 = Regulator 3 will Start in Sequence State 4			
REG4SQ4	3	R/W	0					
KEG43Q4	3		0	0 = No Start	1 = Regulator 4 will Start in Sequence State 4			
REG5SQ4	4	R/W	1					
NE055Q4	4	17/10		0 = No Start	1 = Regulator 5 will Start in Sequence State 4			
REG6SQ4	5	R/W	0					
NE60504	5	17/77	0	0 = No Start	1 = Regulator 6 will Start in Sequence State 4			
	6	R/W	0	Reserved				
	7	R/W	0	Reserved				

#### Table 18. Sequence State 5 Register

Register Name		SEQ5_F	REG	Sequence Register				
Address				0x15'h				
Field	bit	R/W	Default	Description				
DEC1805	0		0					
REG1SQ5	0	R/W	0	0 = No Start	1 = Regulator 1 will Start in Sequence State 5			
REG2SQ5	1	R/W	0					
REG23Q3	I		U	0 = No Start	1 = Regulator 2 will Start in Sequence State 5			
REG3SQ5	2	R/W	0					
REG33Q3	2		U	0 = No Start	1 = Regulator 3 will Start in Sequence State 5			
REG4SQ5	3	R/W	0					
REG43Q3	3		0	0 = No Start	1 = Regulator 4 will Start in Sequence State 5			
REG5SQ5	4	R/W	0					
REG33Q3	4		0	0 = No Start	1 = Regulator 5 will Start in Sequence State 5			
REG6SQ5	5	R/W	0					
REGOSQS	5	r./ v v	0	0 = No Start	1 = Regulator 6 will Start in Sequence State 5			
	6	R/W	0	Reserved				
	7	R/W	0	Reserved				

Register Name		SEQ6_F	REG	Sequence Register				
Address				0x16'h				
Field	bit	R/W	Default	Description				
REC1806	0	R/W	0					
REG1SQ6	0	K/VV	0	0 = No Start	1 = Regulator 1 will Start in Sequence State 6			
REG2SQ6	1	R/W	0					
REG23Q0	I		U	0 = No Start	1 = Regulator 2 will Start in Sequence State 6			
REG3SQ6	2	R/W	0					
REGSSQU	2		0	0 = No Start	1 = Regulator 3 will Start in Sequence State 6			
REG4SQ6	3	R/W	0					
NE043Q0	5	17/10	0	0 = No Start	1 = Regulator 4 will Start in Sequence State 6			
REG5SQ6	4	R/W	0					
REGSSQU	4		0	0 = No Start	1 = Regulator 5 will Start in Sequence State 6			
REG6SQ6	5	R/W	1					
REGOSQU	5	17/10	1	0 = No Start	1 = Regulator 6 will Start in Sequence State 6			
	6	R/W	0	Reserved				
	7	R/W	0	Reserved				

### Table 19. Sequence State 6 Register

### Delay Register (17'h)

The STDEL register sets the delay between powering up of each regulator at initial power up (see Figure 19). Once all the internal power good registers PGOOD[1-6] are all "1", then the global PG pin goes high without delay.

The PORDEL register sets the delay for the POR flag pin. The POR delay time starts as soon as AVIN pin voltage rises above the system UVLO upper threshold set by the PORUP register (21'h). The POR output goes low without delay if AVIN falls below the lower UVLO threshold set by the PORDN register (22'h).

#### Table 20. Delay Register

Register Name	DE	LAY_CN	TL_REG	L_REG Delay Register					
Address				0x17'h					
Field	bit	R/W	Default	Description					
				Delay Time from (	)ms to 7ms in 1ms i	ncrement			
STDEL	2:0	R/W	001 (1ms)	000 = 0ms	010 = 2ms	100 = 4ms	110 = 6ms		
			(1110)	001 = 1ms	011 = 3ms	101 = 5ms	111 = 7ms		
		R/W		Delay Time from 5ms to 160ms in 5ms increment					
				00000 = 5ms	01000 = 45ms	10000 = 85ms	11000 = 125ms		
				00001 = 10ms	01001 = 50ms	10001 = 90ms	11001 = 130ms		
				00010 = 15ms	01010 = 55ms	10010 = 95ms	11010 = 135ms		
PORDEL	7:3		00011 (20ms)	00011 = 20ms	01011 = 60ms	10011 = 100ms	11011 = 140ms		
			(_00)	00100 = 25ms	01100 = 65ms	10100 = 105ms	11100 = 145ms		
				00101 = 30ms	01101 = 70ms	10101 = 110ms	11101 = 150ms		
				00110 = 35ms	01110 = 75ms	10110 = 115ms	11110 = 155ms		
			00111 = 40ms	01111 = 80ms	10111 = 120ms	11111 = 160ms			

## Soft-Start Registers (18'h – 1A'h)

When regulator(n) is turned on from either the Enable Register (04'h) in NORMAL mode or from the Standby Register (03'h) in STANDBY mode, then the three REG(n)SS soft-start bits are used to control both the rising and falling ramp rate of the outputs.

In NORMAL mode, the outputs are stepped from the current regulator voltage settings to a newly-programmed regulator voltage setting or to the default value.

On power-up, the regulator voltage output is set to the lowest possible voltage setting which is 3F'h. The voltage regulator will change by one step or increment at a time. The amount of time between each step is controlled by the soft-start registers. Table 21 details the amount of time for each encoded soft-start value.

	R/W	Default	Description					
			Soft-Start Time from 4µs to 512µs					
SS_SPEED = 0	SPEED = 0 R/W 0	000	000 = 4µs	010 = 16µs	100 = 64µs	110 = 256µs		
			001 = 8μs 011 = 32μs 101 = 128μs 111 = 512μs					
			Soft-Start Time from	m 8µs to 1024µs				
SS_SPEED = 1	R/W 000		000 = 8µs	010 = 32µs	100 = 128µs	110 = 512µs		
			001 = 16µs	011 = 64µs	101 = 256µs	111 = 1024µs		

#### Table 21. Soft-Start Register Speed Settings

#### Table 22. Soft-Start Register OUT1 and OUT2

Register Name	SS1-2_REG Soft-Start Register for V <sub>OUT1</sub> and V <sub>OUT2</sub>				OUT2		
Address				0x18'h			
Field	bit	R/W	Default	Description			
DE0400	2.0		001	OUT1 Soft-Start Time			
REG1SS	2:0	R/W	(8µs)	See Table 19 for Soft-Start Settings			
DECOSO	5.2		001	OUT2 Soft-Start Time			
REG2SS	5:3	R/W	(8µs)	See Table 19 for Soft-Start Settings			
	6	R/W	0	Reserved			
	7		0	Set the speed of the clock to slow or	fast for different clock division, see Table 19.		
SS_SPEED	/	R/W	0	0 = Slow Speed 1 = Fast Speed			

#### Table 23. Soft-Start Register OUT3 and OUT4

Register Name	:	SS3-4_F	REG	Soft-Start Register for V <sub>OUT3</sub> and V <sub>OUT4</sub>			
Address				0x19'h			
Field	bit	R/W	Default	Description			
DECOSO	0.0		001	OUT3 Soft-Start Time			
REG3SS	2:0	R/W	(8µs)	See Table 19 for Soft-Start Settings			
REG4SS	5.2	R/W	001	OUT4 Soft-Start Time			
REG435	5:3	K/W	(8µs)	See Table 19 for Soft-Start Settings			
	6	R/W	0	Reserved			
	7	R/W	0	Reserved			

Register Name		SS5-6_F	REG	Soft-Start Register for V <sub>OUT5</sub> and V <sub>OUT6</sub>			
Address				0x1A'h			
Field	bit	R/W	Default	Description			
REG5SS	2:0	001		OUT5 Soft-Start Time			
REG555	2.0	R/W	(8µs)	See Table 19 for Soft-Start Settings			
REG6SS	5.2	R/W	010	OUT6 Soft-Start Time			
REG055	5:3	R/W	(16µs)	See Table 19 for Soft-Start Settings			
	6	R/W	0	Reserved			
	7	R/W	0	Reserved			

## Table 24. Soft-Start Register OUT5 and OUT6

## Current-Limit (Normal Mode) Registers (1B'h - 1D'h)

This register is use to set the current limit for each DC-to-DC regulator in normal mode operation.

Register Name	ILI	MIT_1-2	_REG	Current-Limit Register for V <sub>OUT1</sub> and V <sub>OUT2</sub>				
Address				0x1B'h				
Field	bit	R/W	Default	Description				
				Normal current-lin	nit for regulator 1 fro	om 8.6A to 1.1A in (	0.5A decrements	
			1001	0000 = 8.6A	0100 = 6.6A	1000 = 4.6A	1100 = 2.6 A	
REG1CL	3:0	R/W	1001 (4.1A)	0001 = 8.1A	0101 = 6.1A	1001 = 4.1A	1101 = 2.1A	
				0010 = 7.6A	0110 = 5.6A	1010 = 3.6A	1110 = 1.6A	
				0011 = 7.1A	0111 = 5.1A	1011 = 3.1A	1111 = 1.1A	
				Normal current-lin	nit for regulator 2 fro	om 8.6A to 1.1A in (	0.5A decrements	
			1001	0000 = 8.6A	0100 = 6.6A	1000 = 4.6A	1100 = 2.6 A	
REG2CL	7:4	R/W	1001 (4.1A)	0001 = 8.1A	0101 = 6.1A	1001 = 4.1A	1101 = 2.1A	
		(4.1A)	0010 = 7.6A	0110 = 5.6A	1010 = 3.6A	1110 = 1.6A		
				0011 = 7.1A	0111 = 5.1A	1011 = 3.1A	1111 = 1.1A	

Table 25. Current-Limit Register IOUT1 and IOUT2

Table 26. Current-Limit Register IOUT3 and IOUT4

Register Name	ILI	MIT_3-4	_REG	Current-Limit Register for V <sub>OUT3</sub> and V <sub>OUT4</sub>				
Address				0x1C'h				
Field	bit	R/W	Default	Description				
				Normal current-li	mit for regulator 3 fr	om 8.6A to 1.1A in (	0.5A decrements	
			1001 (4.1A)	0000 = 8.6A	0100 = 6.6A	1000 = 4.6A	1100 = 2.6 A	
REG3CL	3:0	R/W		0001 = 8.1A	0101 = 6.1A	1001 = 4.1A	1101 = 2.1A	
				0010 = 7.6A	0110 = 5.6A	1010 = 3.6A	1110 = 1.6A	
				0011 = 7.1A	0111 = 5.1A	1011 = 3.1A	1111 = 1.1A	
			0101 (6.1A)	Normal current-limit for regulator 4 from 8.6A to 1.1A in 0.5A decrements				
				0000 = 8.6A	0100 = 6.6A	1000 = 4.6A	1100 = 2.6 A	
REG4CL	7:4	R/W		0001 = 8.1A	0101 = 6.1A	1001 = 4.1A	1101 = 2.1A	
				0010 = 7.6A	0110 = 5.6A	1010 = 3.6A	1110 = 1.6A	
				0011 = 7.1A	0111 = 5.1A	1011 = 3.1A	1111 = 1.1A	

## Table 27. Current-Limit Register IOUT 5 and IOUT6

Register Name	IL	IMIT_5-6	6_REG	Current-Limit Register for VOUT5 and VOUT6				
Address				0x1D'h				
Field	bit	R/W	Default	Description				
				Normal current-lin	nit for regulator 5 fro	om 8.6A to 1.1A in (	0.5A decrements	
REG5CL		R/W	1001 (4.1A)	0000 = 8.6A	0100 = 6.6A	1000 = 4.6A	1100 = 2.6 A	
	3:0			0001 = 8.1A	0101 = 6.1A	1001 = 4.1A	1101 = 2.1A	
				0010 = 7.6A	0110 = 5.6A	1010 = 3.6A	1110 = 1.6A	
				0011 = 7.1A	0111 = 5.1A	1011 = 3.1A	1111 = 1.1A	
			0.1.1	Current limit from 2.6A to 1.78A in 0.12A decrements				
DECCO	6:4	R/W	011 (2.24A)	000 = 2.6A	010 = 2.36A	100 = 2.12A	110 = 1.88A	
REG6CL				001 = 2.48A	011 = 2.24A	101 = 2.00A	111 = 1.76A	
	7	R/W	0	0 = Current Limit	On	1 = Current Limit	Off	

This register is used to set the current limit for each DC-to-DC regulator when in standby (STBY) mode operation.

Register Name	STB	Y_ILIMIT	_1-2_REG	Standby Current-Limit Register for $V_{\text{OUT1}}$ and $V_{\text{OUT2}}$				
Address				0x1E'h				
Field	bit	R/W	Default	Description				
				Standby current	limit for regulator 1	from 8.6A to 1.1A in	0.5A decrements	
			1001 (4.1A)	0000 = 8.6A	0100 = 6.6A	1000 = 4.6A	1100 = 2.6 A	
SB1CL 3	3:0	R/W		0001 = 8.1A	0101 = 6.1A	1001 = 4.1A	1101 = 2.1A	
				0010 = 7.6A	0110 = 5.6A	1010 = 3.6A	1110 = 1.6A	
				0011 = 7.1A	0111 = 5.1A	1011 = 3.1A	1111 = 1.1A	
		R/W		Standby current limit for regulator 2 from 8.6A to 1.1A in 0.5A decrements				
			4004	0000 = 8.6A	0100 = 6.6A	1000 = 4.6A	1100 = 2.6 A	
SB2CL	7:4		1001 (4.1A)	0001 = 8.1A	0101 = 6.1A	1001 = 4.1A	1101 = 2.1A	
				0010 = 7.6A	0110 = 5.6A	1010 = 3.6A	1110 = 1.6A	
				0011 = 7.1A	0111 = 5.1A	1011 = 3.1A	1111 = 1.1A	

Table 28. Standby Current-Limit Register IOUT1 and IOUT2

#### Table 29. Standby Current-Limit Register IOUT3 and IOUT4

Register Name	STBY_ILIMIT_3-4_REG			Standby Current-Limit Register for $V_{OUT3}$ and $V_{OUT4}$						
Address				0x1F'h						
Field	bit	R/W	Default	Description	Description					
				Standby current li	mit for regulator 3 fi	rom 8.6A to 1.1A in	0.5A decrements			
		R/W	1001	0000 = 8.6A	0100 = 6.6A	1000 = 4.6A	1100 = 2.6 A			
SB3CL :	3:0		1001 (4.1A)	0001 = 8.1A	0101 = 6.1A	1001 = 4.1A	1101 = 2.1A			
				0010 = 7.6A	0110 = 5.6A	1010 = 3.6A	1110 = 1.6A			
				0011 = 7.1A	0111 = 5.1A	1011 = 3.1A	1111 = 1.1A			
		R/W	0101 (6.1A)	Standby current limit for regulator 4 from 8.6A to 1.1A in 0.5A decrements						
				0000 = 8.6A	0100 = 6.6A	1000 = 4.6A	1100 = 2.6 A			
SB4CL	7:4			0001 = 8.1A	0101 = 6.1A	1001 = 4.1A	1101 = 2.1A			
				0010 = 7.6A	0110 = 5.6A	1010 = 3.6A	1110 = 1.6A			
				0011 = 7.1A	0111 = 5.1A	1011 = 3.1A	1111 = 1.1A			

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able 30. Standby Current-Limit Register Iouts and Ioute									
Register Name	STE	BY_ILIMI	T_5-6_REG	Standby Current-Limit Register for VOUT5 and VOUT6					
Address				0x20'h	0x20'h				
Field	bit	R/W	Default	Description					
				Standby current li	mit for regulator 5 f	rom 8.6A to 1.1A in	0.5A decrements		
			1001 (4.1A)	0000 = 8.6A	0100 = 6.6A	1000 = 4.6A	1100 = 2.6 A		
SB5CL	3:0	R/W		0001 = 8.1A	0101 = 6.1A	1001 = 4.1A	1101 = 2.1A		
				0010 = 7.6A	0110 = 5.6A	1010 = 3.6A	1110 = 1.6A		
				0011 = 7.1A	0111 = 5.1A	1011 = 3.1A	1111 = 1.1A		
				Current limit from 2.6A to 1.78A in 0.12A decrements					
SB6CL	6:4	R/W	011 (2.24A)	000 = 2.6A	010 = 2.36A	100 = 2.12A	110 = 1.88A		
				001 = 2.48A	011 = 2.24A	101 = 2.00A	111 = 1.76A		
	7	R/W	0	0 = Current Limit On		1 = Current Limit Off			

### Table 30. Standby Current-Limit Register IOUT5 and IOUT6

## Power-on-Reset (POR) Threshold Voltage Setting Register (21'h and 22'h)

This register is used to set the rising and falling threshold of power-on-reset (POR) comparator. The POR threshold voltage setting is based on the logic level of the VSLT pin in addition to the register bits. Refer to Table 20 for POR time delay settings.

Table 31. Rising and Falling Power-on-Reset Threshold Volta	ae Settinas
Table off Rioling and Falling Forer off Recet Theorem	ge oouinge

				Rising and Falling Power-On-Reset Threshold Voltage Setting					
	bit	R/W	Default	Description					
				3.3V to 2.3V in 50mV decrements					
				00000 = 3.25V	01000 = 2.85V	10000 = 2.45V	11000 = 2.25V		
				00001 = 3.20V	01001 = 2.80V	10001 = 2.40V	11001 = 2.25V		
				00010 = 3.15V	01010 = 2.75V	10010 = 2.35V	11010 = 2.25V		
VSCLT = 0	4:0	R/W	00000	00011 = 3.10V	01011 = 2.70V	10011 = 2.30V	11011 = 2.25V		
				00100 = 3.05V	01100 = 2.65V	10100 = 2.25V	11100 = 2.25V		
				00101 = 3.00V	01101 = 2.60V	10101 = 2.25V	11101 = 2.25V		
				00110 = 2.95V	01110 = 2.55V	10110 = 2.25V	11110 = 2.25V		
				00111 = 2.90V	01111 = 2.50V	10111 = 2.25V	11111 = 2.25V		
					4.3V to 3.3V in 50	mV decrements			
				00000 = 4.25V	01000 = 3.85V	10000 = 3.45V	11000 = 3.25V		
				00001 = 4.20V	01001 = 3.80V	10001 = 3.40V	11001 = 3.25V		
				00010 = 4.15V	01010 = 3.75V	10010 = 3.35V	11010 = 3.25V		
VSCLT = 1	4:0	R/W	00000	00011 = 4.10V	01011 = 3.70V	10011 = 3.30V	11011 = 3.25V		
				00100 = 4.05V	01100 = 3.65V	10100 = 3.25V	11100 = 3.25V		
				00101 = 4.00V	01101 = 3.60V	10101 = 3.25V	11101 = 3.25V		
				00110 = 3.95V	01110 = 3.55V	10110 = 3.25V	11110 = 3.25V		
				00111 = 3.90V	01111 = 3.50V	10111 = 3.25V	11111 = 3.25V		

The three most significant bits [7:5] in registers 21'h and 22'h are used to mask the output voltage power-good flag after the start-up sequenced is finished.

#### Table 32. Power-on-Reset Rising Threshold Voltage Setting Register (21'h)

Register Name		PORL	JO_REG	Power-on-Reset Falling Threshold				
Address				0x21'h				
Field	bit	R/W	Default	Description				
PORUP	4:0	R/W	01011 (2.7V)	See Table 28				
PGOOD_MASK1	5	R/W	1	0 = Do not mask PGOOD1	1 = Mask PGOOD1			
PGOOD_MASK2	6	R/W	1	0 = Do not mask PGOOD2	1 = Mask PGOOD2			
PGOOD_MASK3	7	R/W	1	0 = Do not mask PGOOD3 1 = Mask PGOOD3				

#### Table 33. Power-on-Reset Falling Threshold Voltage Setting Register (22'h)

Register Name		PORE	N_REG	Power-on-Reset Falling Threshold				
Address				0x22'h				
Field	bit	R/W	Default	Description				
PORDN	4:0	R/W	01101 (2.6V)	See Table 28				
PGOOD_MASK4	5	R/W	1	0 = Do not mask PGOOD4	1 = Mask PGOOD4			
PGOOD_MASK5	6	R/W	1	0 = Do not mask PGOOD5	1 = Mask PGOOD5			
PGOOD_MASK6	7	R/W	1	0 = Do not mask PGOOD6	1 = Mask PGOOD6			

### Pull-Down when Disabled Register (23'h)

This register is used to set the preference of enabling/disabling a pull-down FET when the DC-to-DC regulators are disabled. The pull-down value for buck regulators 1 - 5 is  $90\Omega$ . The pull-down current value for the boost regulator 6 is programmable.

Register Name	PULLDN1-6_REG			Pull-Down when Disabled Register					
Address				0x23'h					
Field	bit	R/W	Default	Description					
	0			Enable/Disable the	pull-down on Regula	tor 1 w	vhen power do	wn	
PULLD1	0	R/W	0	0 = No Pull Down			1 = Pull-Dowr	n	
				Enable/Disable the pull-down on Regulator 2 when power down					
PULLD2	1	R/W	0	0 = No Pull-Down			1 = Pull-Dowr	n	
			0	Enable/Disable the pull-down on Regulator 3 when power-down					
PULLD3	2	R/W 0		0 = No Pull-Down			1 = Pull Down		
				Enable/Disable the pull-down on Regulator 4 when power down					
PULLD4	3	R/W	0	0 = No Pull-Down			1 = Pull-Down		
	4		0	Enable/Disable the pull-down on Regulator 5 when power-down					
PULLD5	4	R/W	0	0 = No Pull-Down			1 = Pull-Down		
	0.5		00	Sets Boost Pull-Dow	n Current Level				
PULLD6C	6:5	R/W	00	00 = 148mA	01 = 111mA 10 = 74mA 1		11 = 37mA		
	7		0	Enable/Disable the	Enable/Disable the pull-down on Regulator 6 when power-down				
PULLD6	7 R/W 0		0 = No Pull-Down			1 = Pull-Down			

### Table 34. Pull-Down when Disabled Register

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